





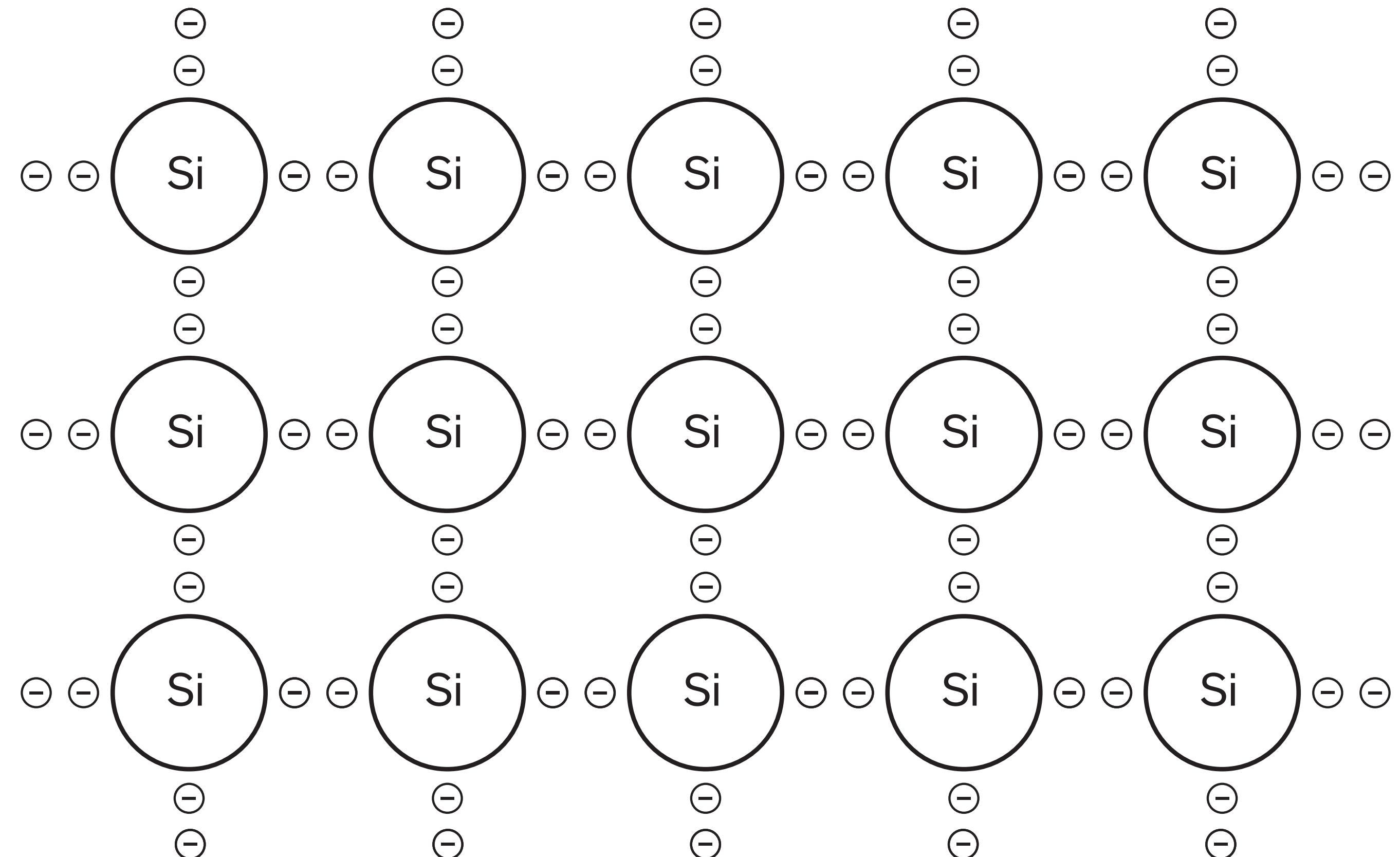
Aufgabe  
Halbleiter  
Transistoren  
MOSFETS

Galvanische Trennung  
Optokoppler  
Relais

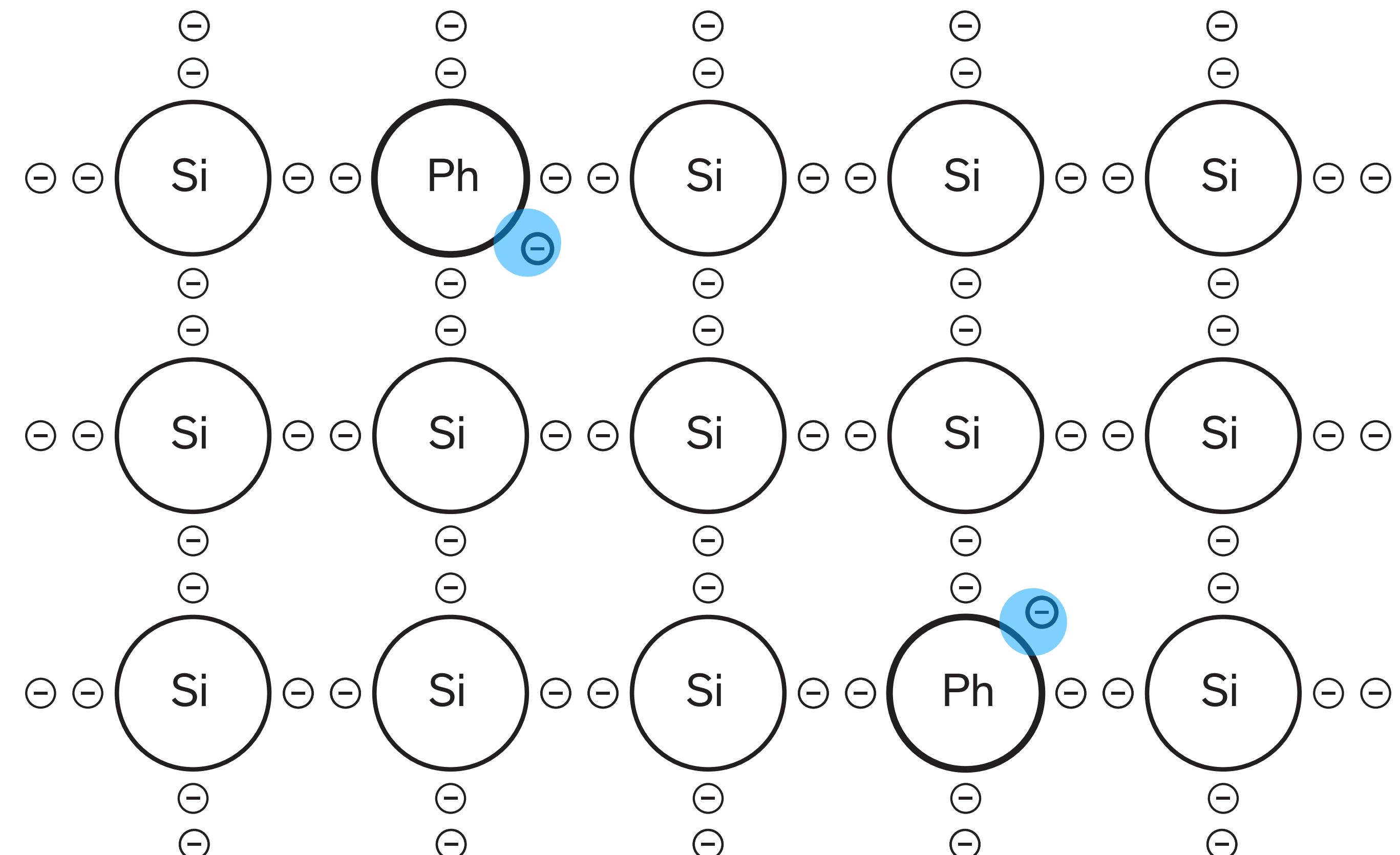
# Aufgabe



Halbleiter

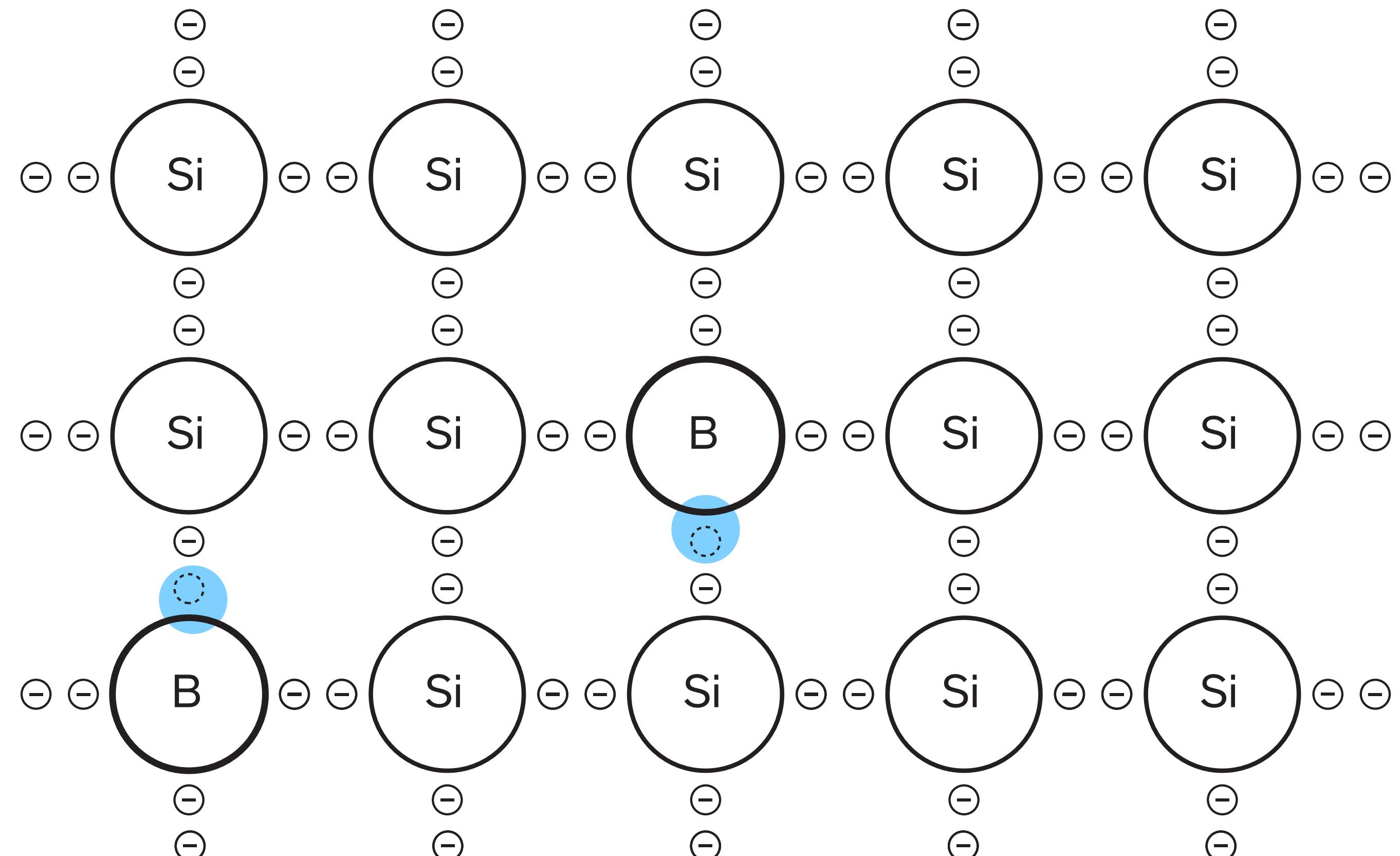


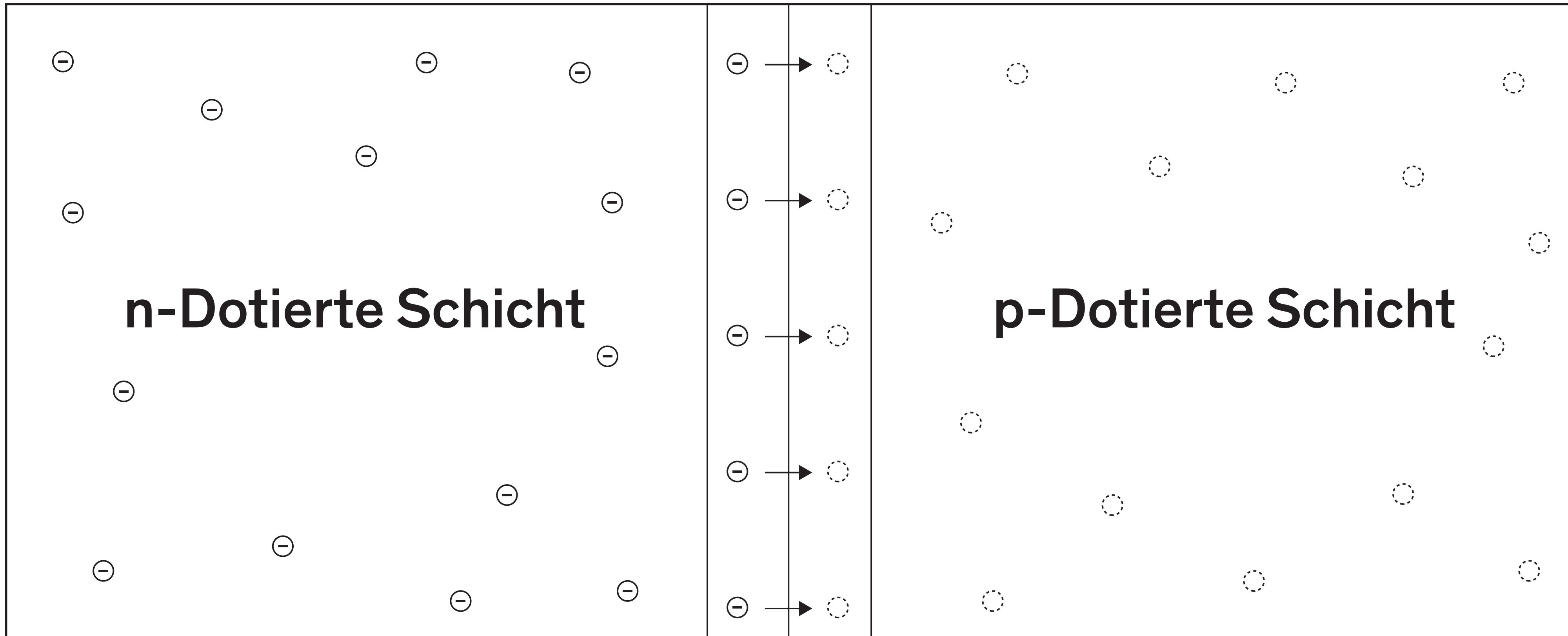
Halbleiter



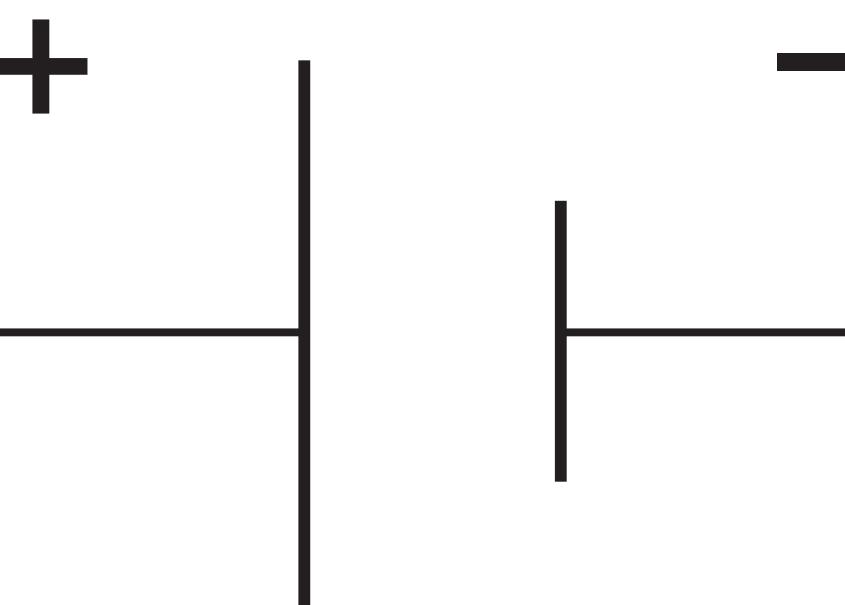
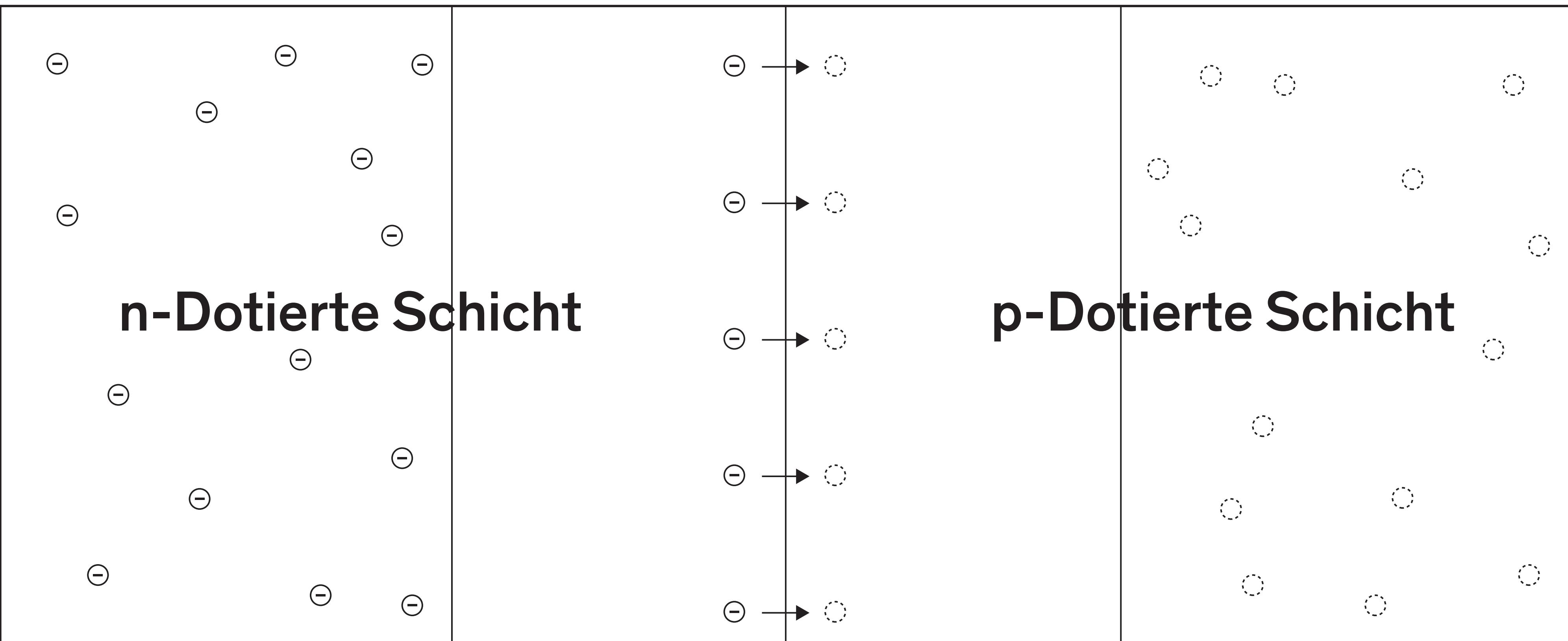
# n-Dotierung

# p-Dotierung

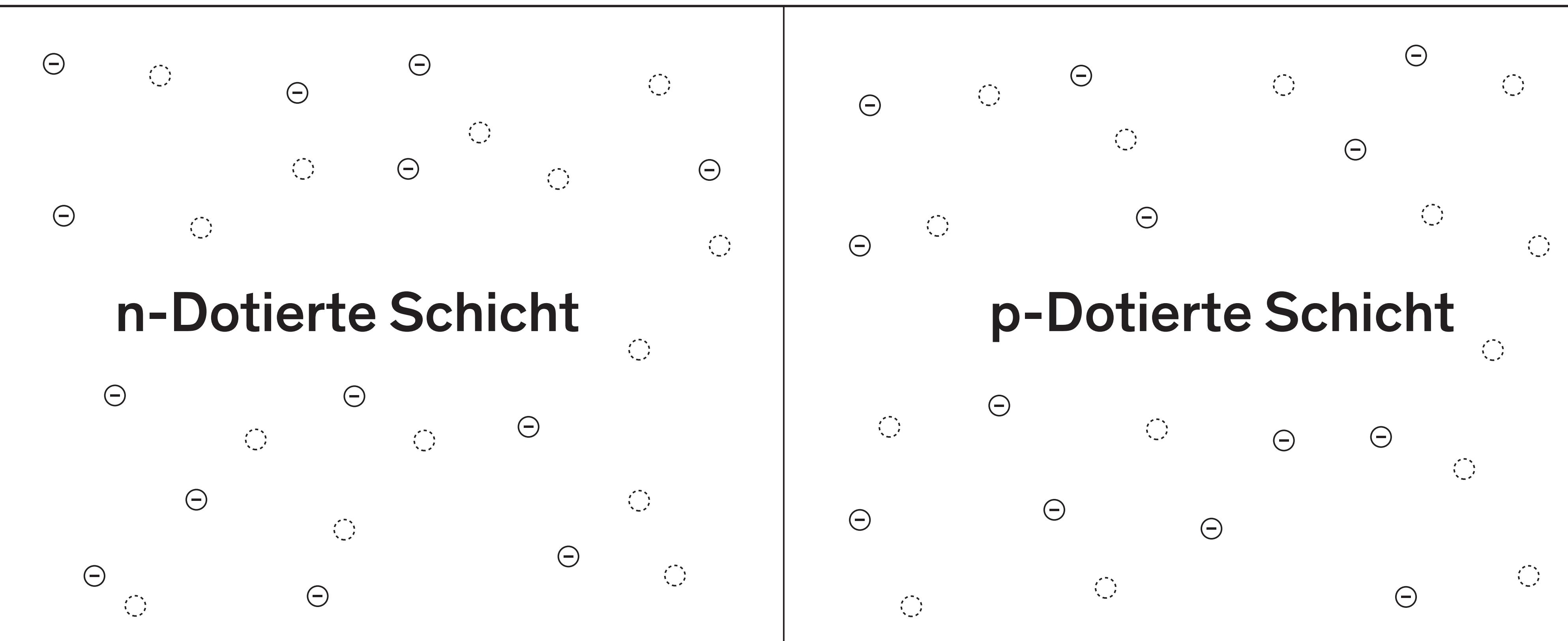




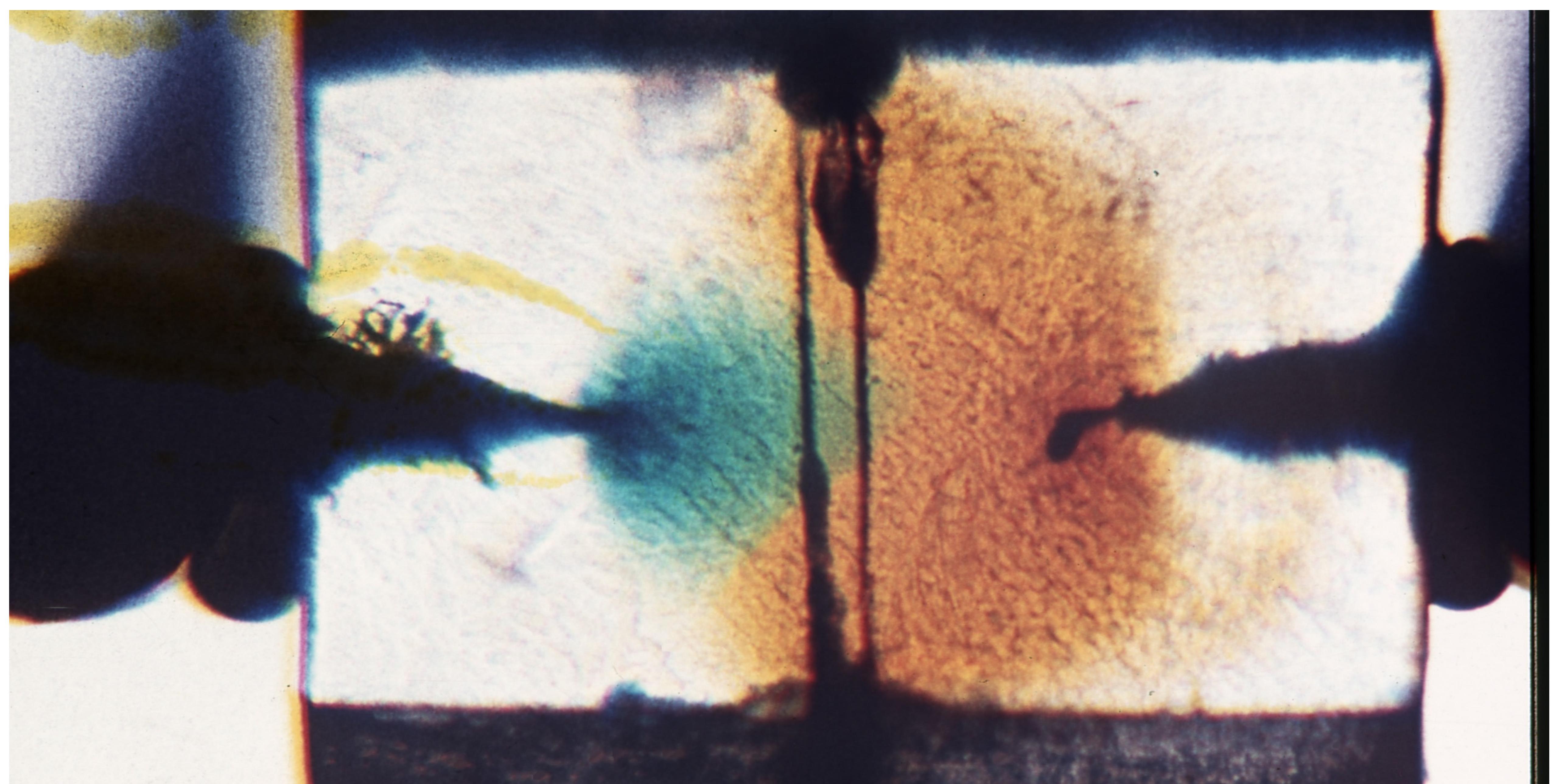
**n-p-Übergang**



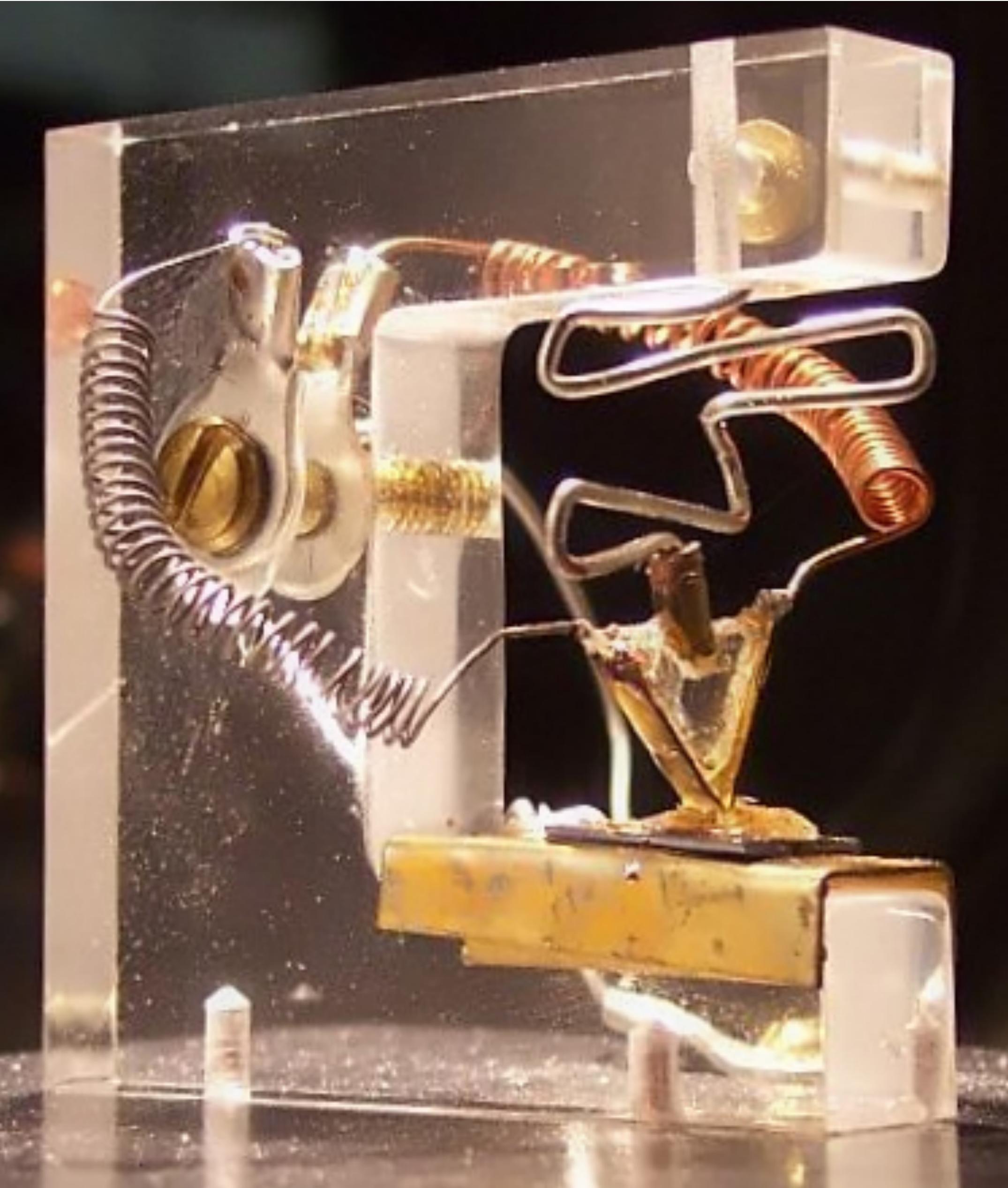
Sperr-Richtung



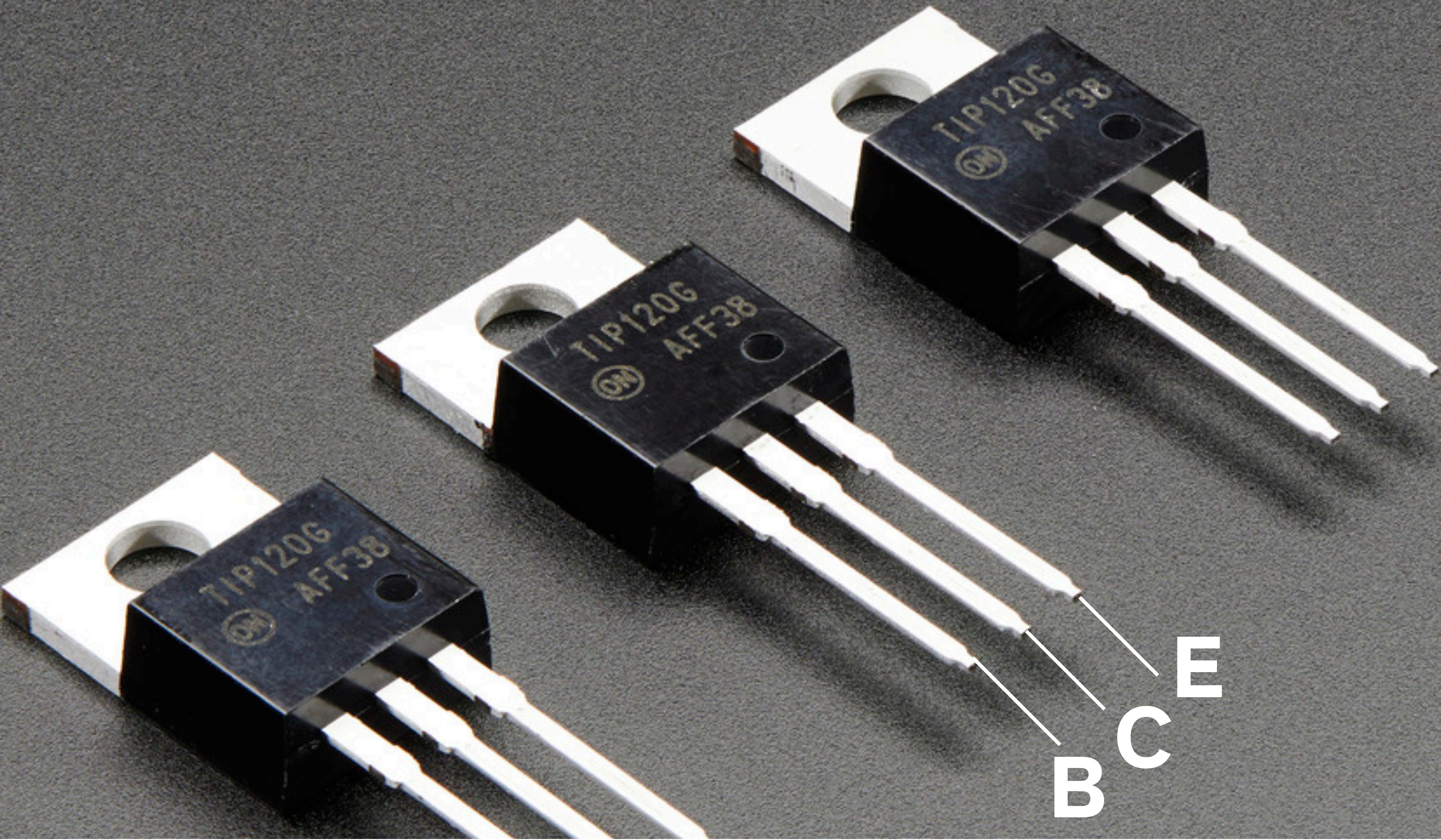
Durchlass-Richtung



n-P-Übergäng

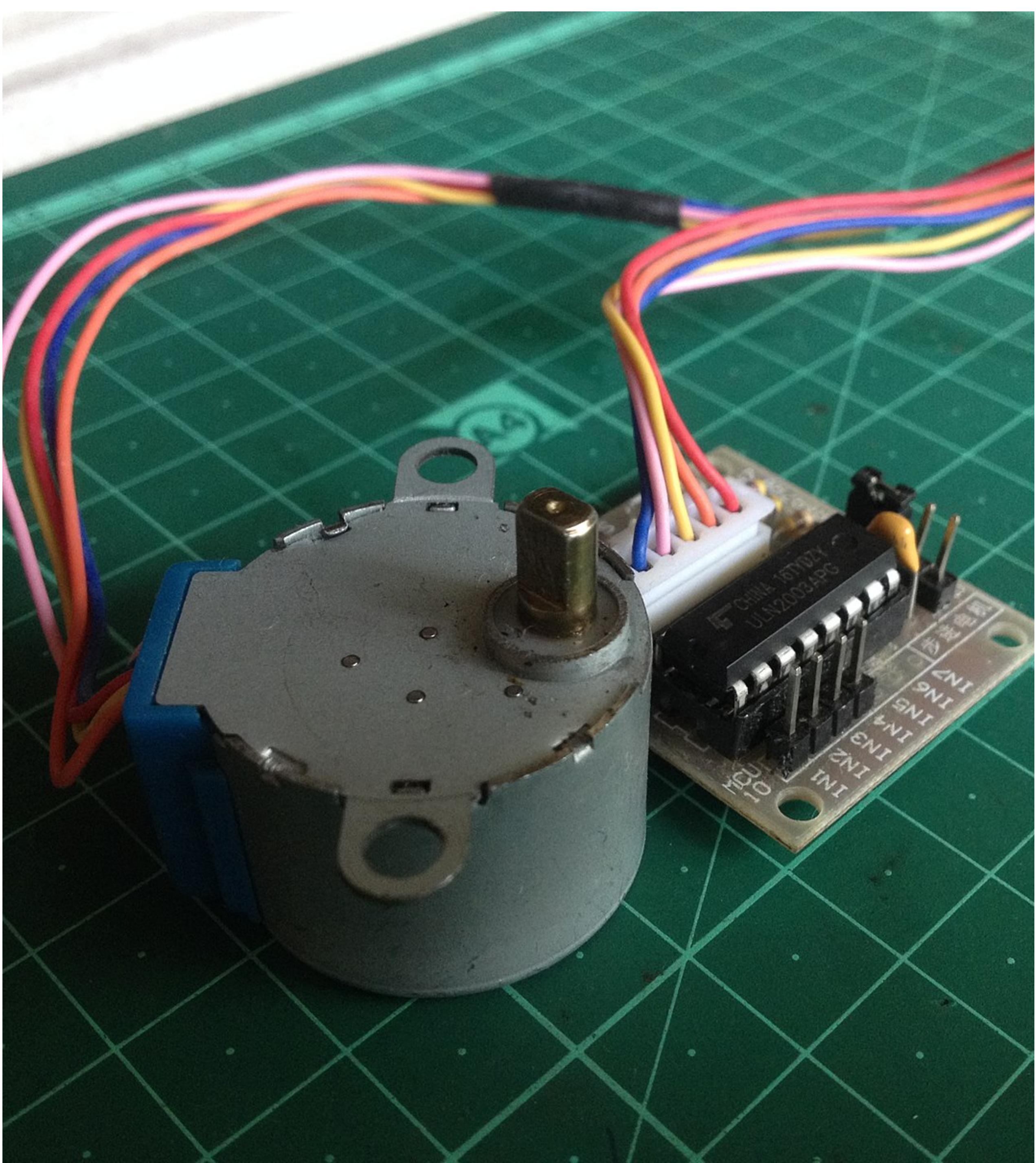


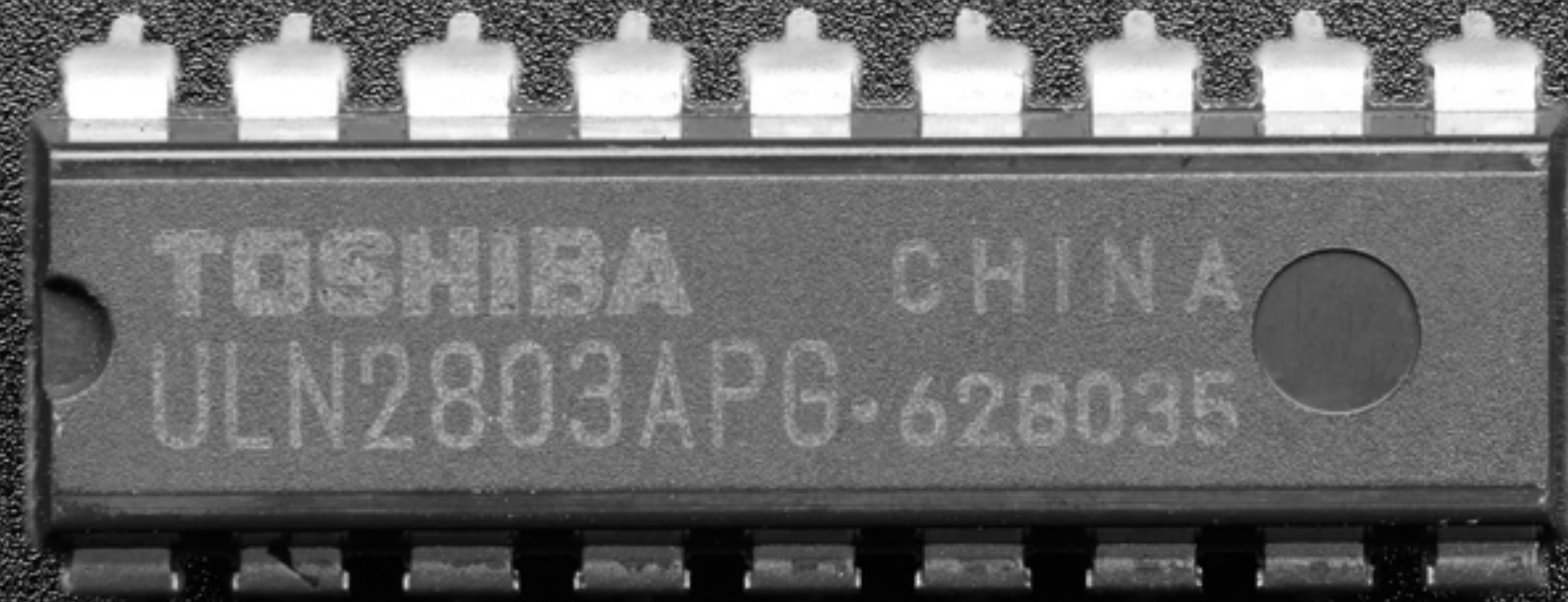
# Transistoren



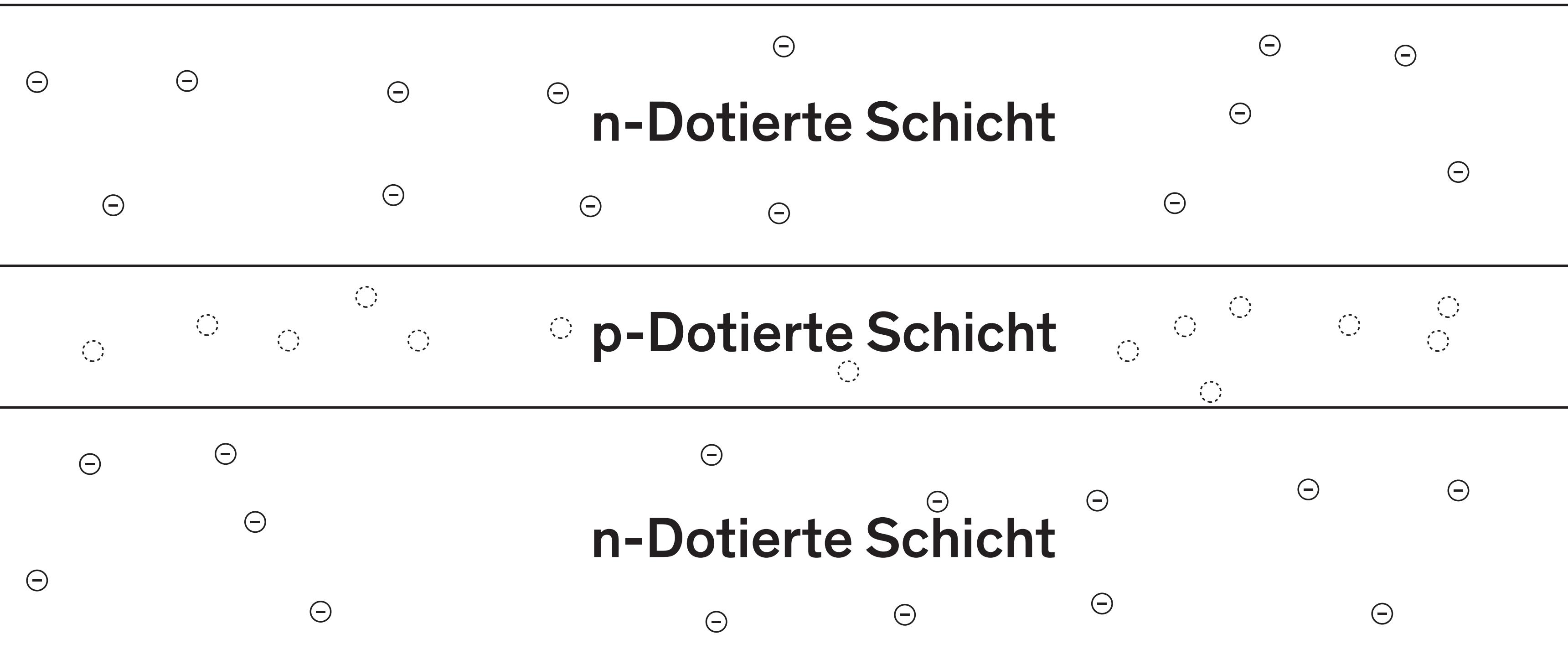
Transistoren

# Transistoren





Transistoren



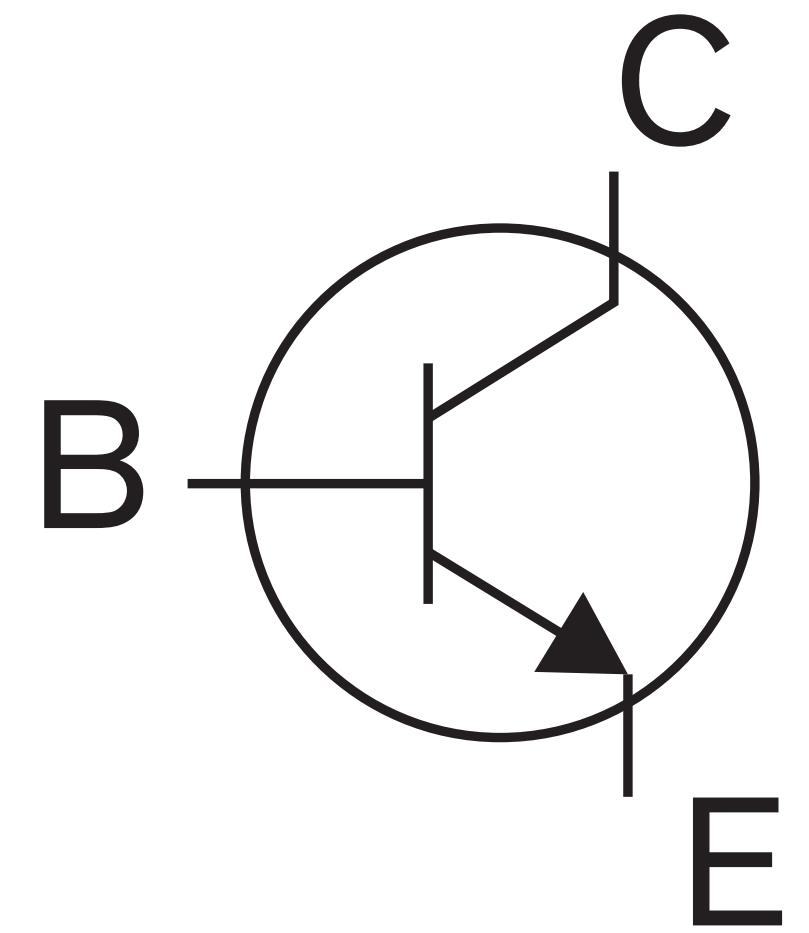
**npn-Transistoren**

Kollektor (C)

Basis (B)

Emitter (E)

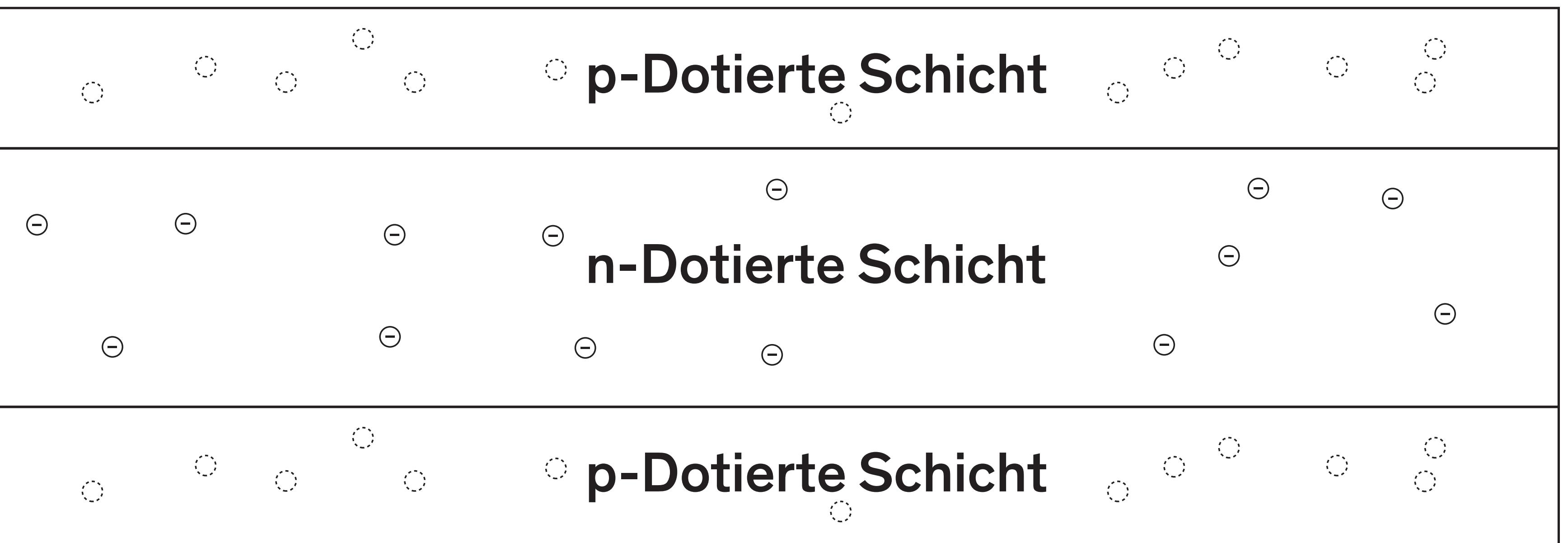
# npn-Transistoren



Kollektor (C)

Basis (B)

Emitter (E)



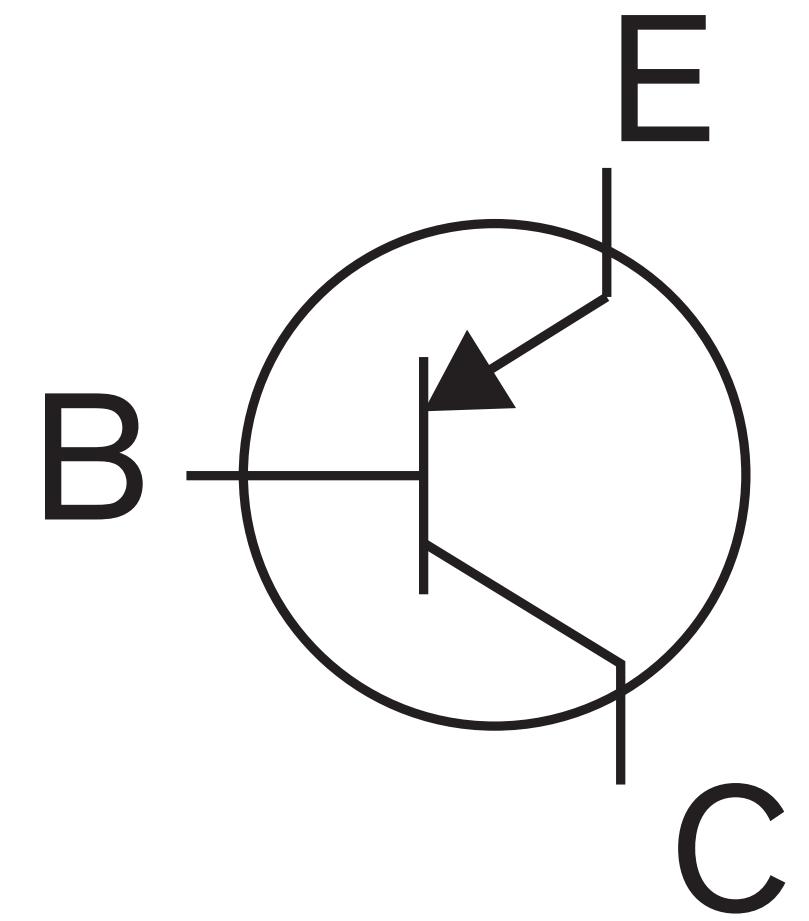
Emitter (E)

Basis (B)

Collector (C)

pnp-Transistoren

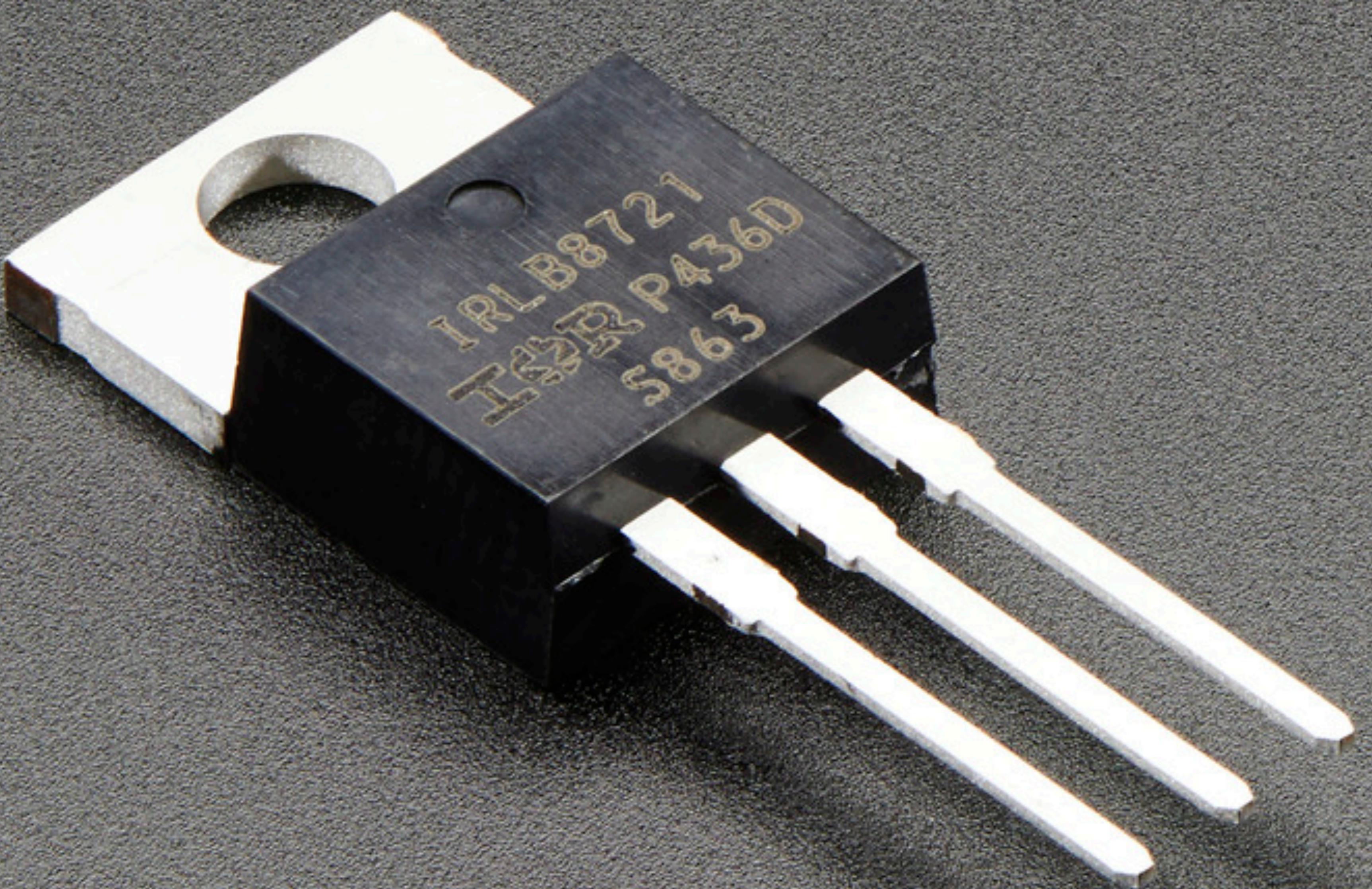
# pnp-Transistoren



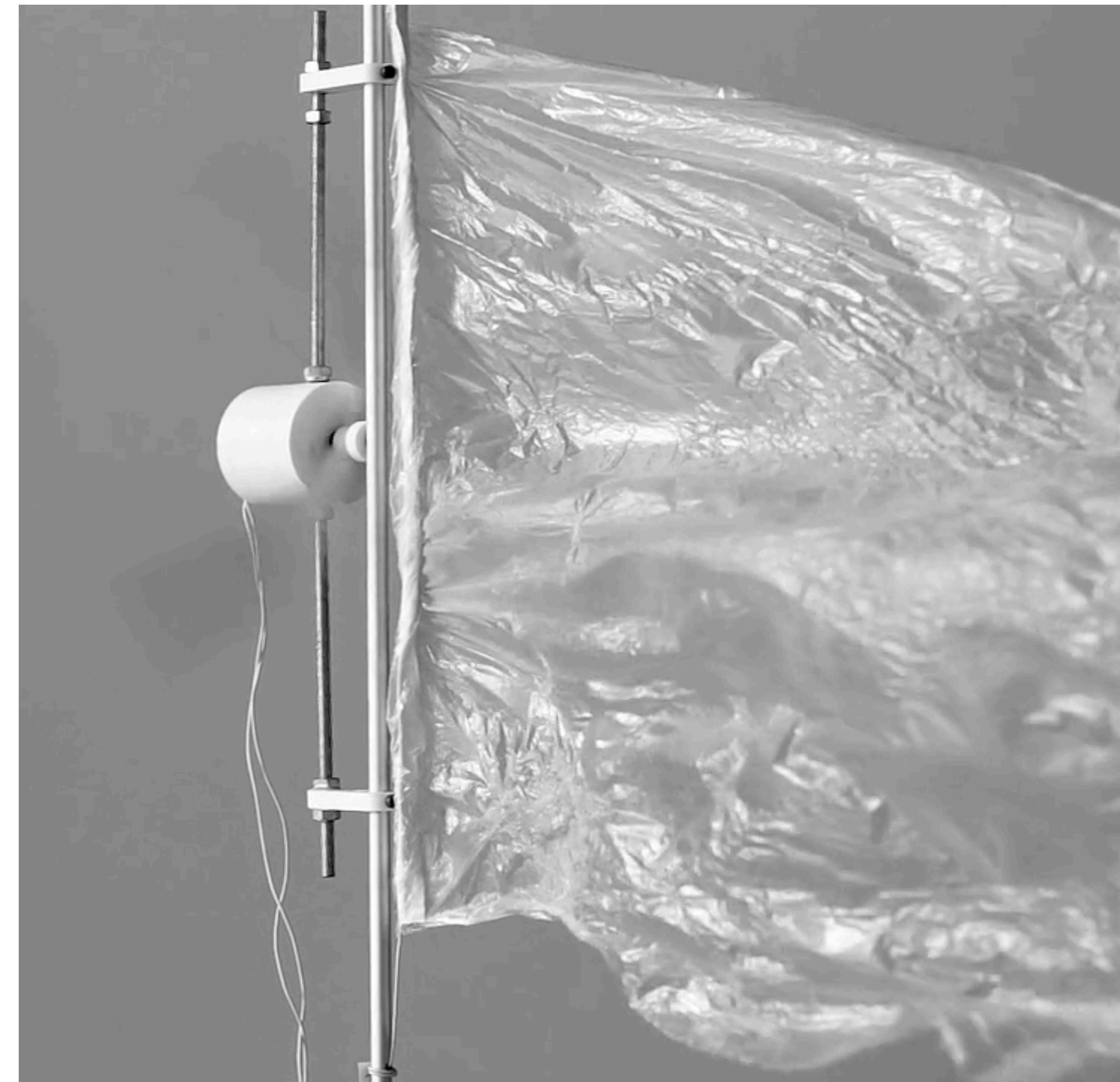
Emitter (E)

Basis (B)

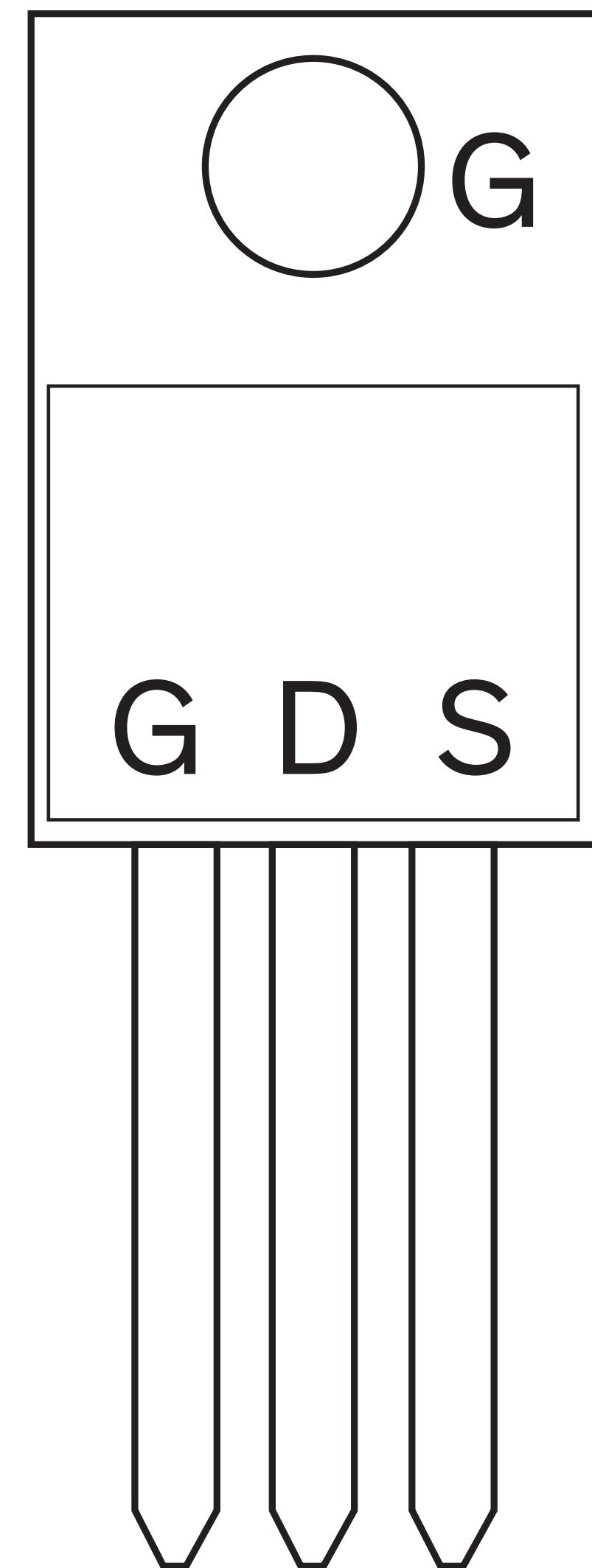
Collector (C)



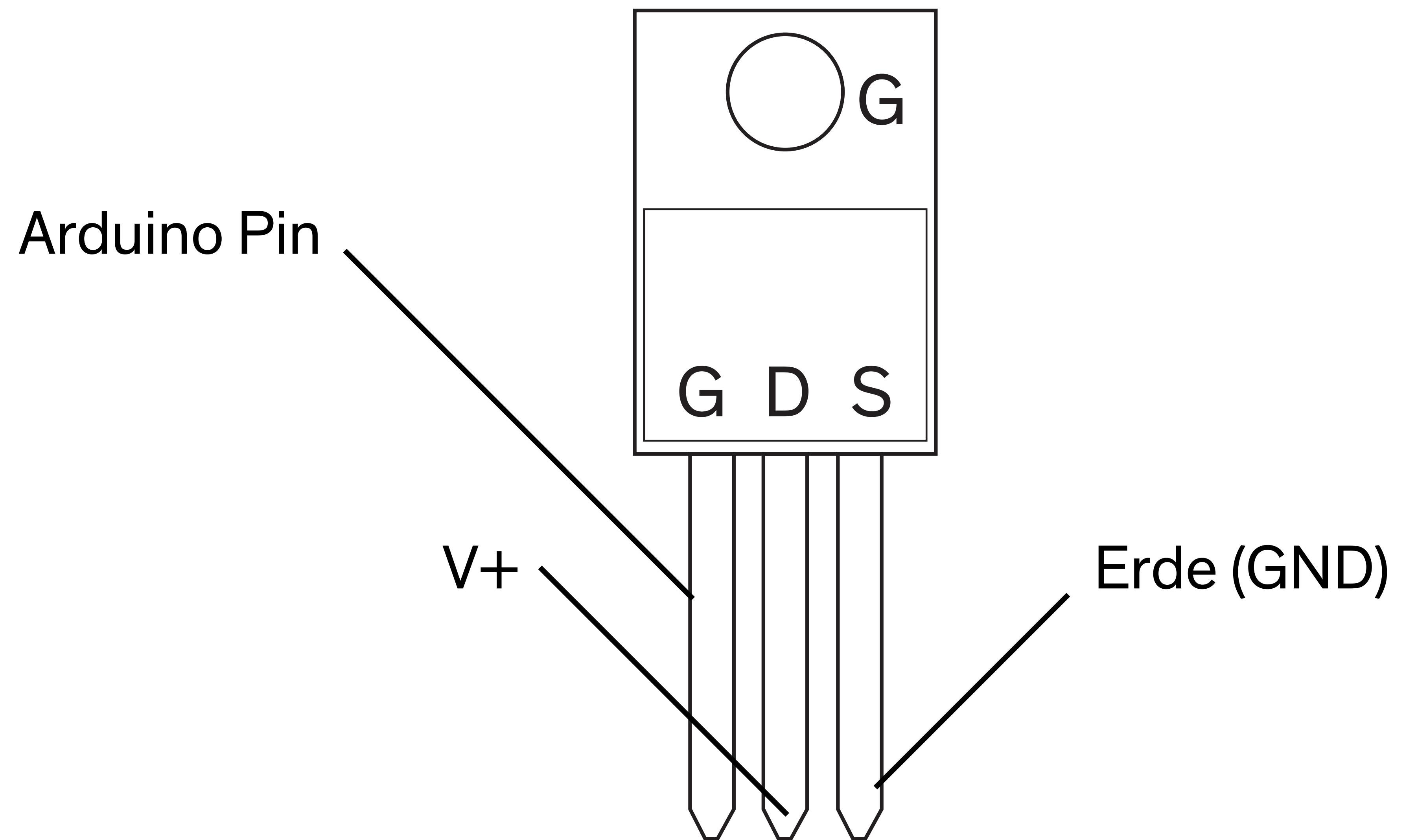
# MOSFETS



# MOSFETS



MOSFETS

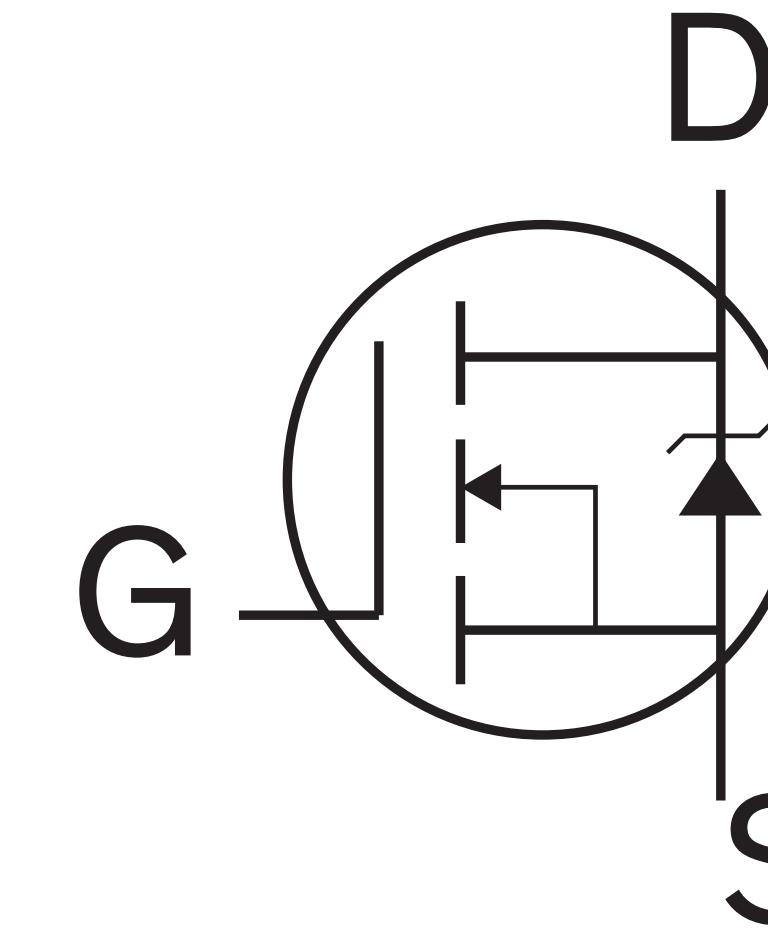


MOSFETS

**IRLZ44N**  
**IRL540N**  
**IRLZ24N**

**IRF522**  
**IRF540**  
**IRF3205**

**MOSFETS**

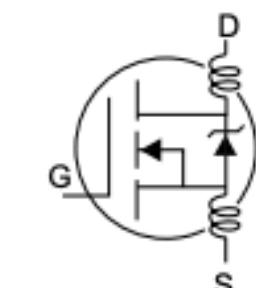


	<b>Parameter</b>	<b>Max.</b>	<b>Units</b>
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	47	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	33	
$I_{DM}$	Pulsed Drain Current ①	160	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation	110	W
	Linear Derating Factor	0.71	W/ $^\circ\text{C}$
$V_{GS}$	Gate-to-Source Voltage	$\pm 16$	V
$E_{AS}$	Single Pulse Avalanche Energy ②	210	mJ
$I_{AR}$	Avalanche Current①	25	A
$E_{AR}$	Repetitive Avalanche Energy①	11	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ ③	5.0	V/ns
$T_J$	Operating Junction and	-55 to + 175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting torque, 6-32 or M3 screw.	10 lbf•in (1.1N•m)	

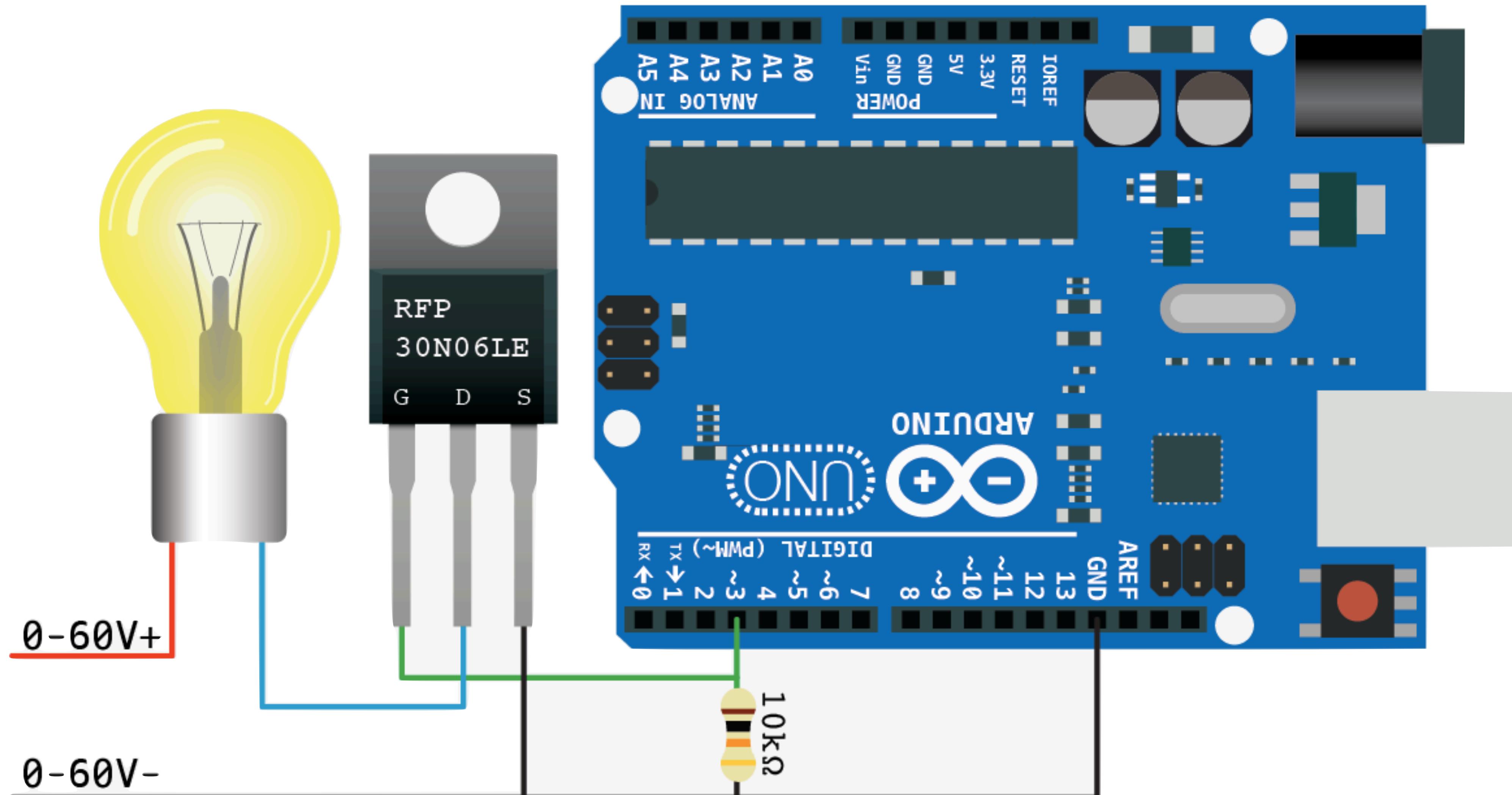
## Thermal Resistance

	<b>Parameter</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Units</b>
$R_{\theta JC}$	Junction-to-Case	—	—	1.4	$^\circ\text{C/W}$
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.50	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	62	

**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

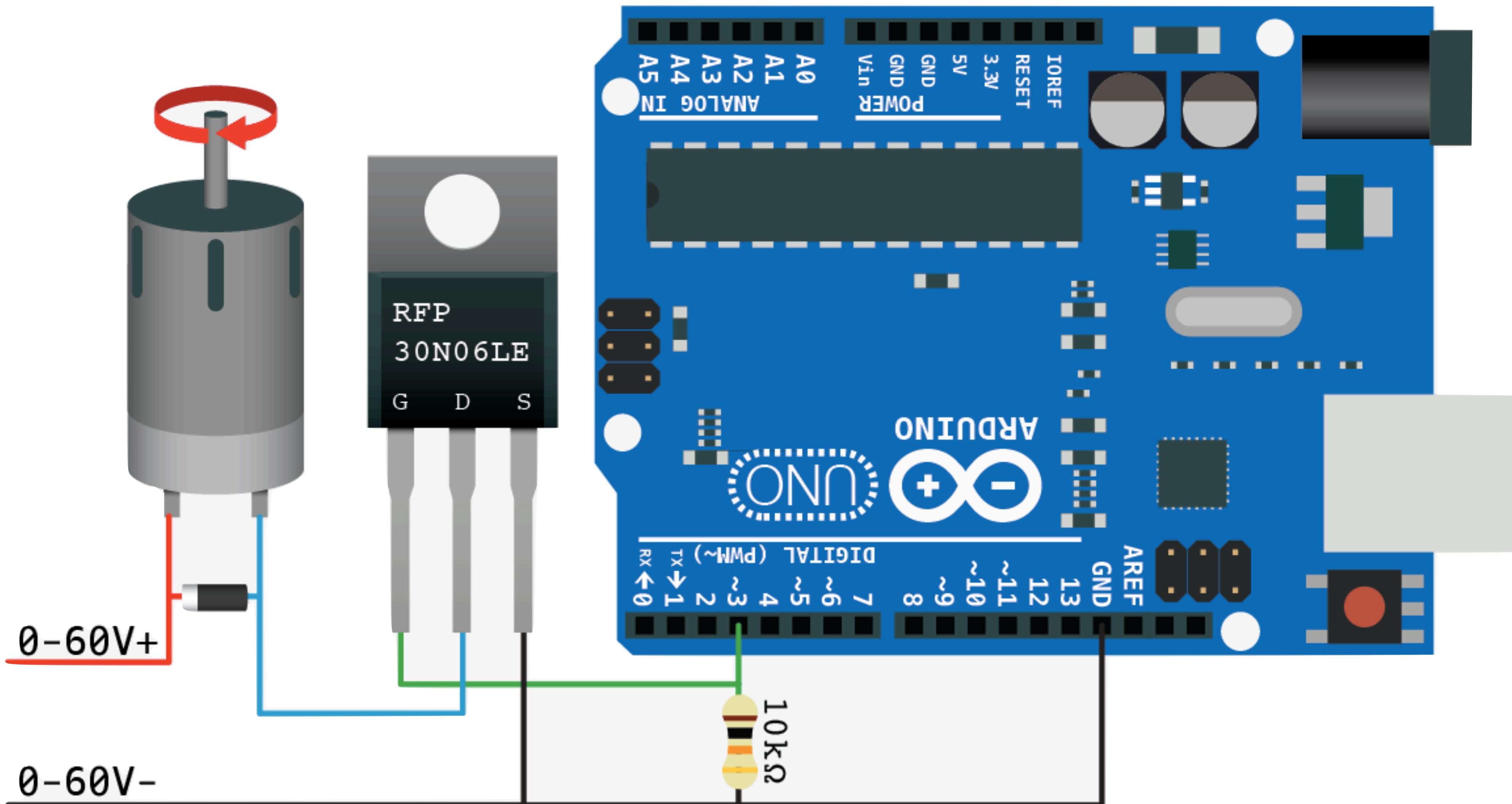
	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	55	—	—	V	$V_{\text{GS}} = 0\text{V}$ , $I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.070	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $I_D = 1\text{mA}$
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	0.022	$\Omega$	$V_{\text{GS}} = 10\text{V}$ , $I_D = 25\text{A}$ ④
		—	—	0.025		$V_{\text{GS}} = 5.0\text{V}$ , $I_D = 25\text{A}$ ④
		—	—	0.035		$V_{\text{GS}} = 4.0\text{V}$ , $I_D = 21\text{A}$ ④
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	1.0	—	2.0	V	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = 250\mu\text{A}$
$g_{\text{fs}}$	Forward Transconductance	21	—	—	S	$V_{\text{DS}} = 25\text{V}$ , $I_D = 25\text{A}$
$I_{\text{DSS}}$	Drain-to-Source Leakage Current	—	—	25	$\mu\text{A}$	$V_{\text{DS}} = 55\text{V}$ , $V_{\text{GS}} = 0\text{V}$
		—	—	250		$V_{\text{DS}} = 44\text{V}$ , $V_{\text{GS}} = 0\text{V}$ , $T_J = 150^\circ\text{C}$
$I_{\text{GSS}}$	Gate-to-Source Forward Leakage	—	—	100	$\text{nA}$	$V_{\text{GS}} = 16\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{\text{GS}} = -16\text{V}$
$Q_g$	Total Gate Charge	—	—	48	$\text{nC}$	$I_D = 25\text{A}$
$Q_{\text{gs}}$	Gate-to-Source Charge	—	—	8.6		$V_{\text{DS}} = 44\text{V}$
$Q_{\text{gd}}$	Gate-to-Drain ("Miller") Charge	—	—	25		$V_{\text{GS}} = 5.0\text{V}$ , See Fig. 6 and 13 ④
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	11	—	$\text{ns}$	$V_{\text{DD}} = 28\text{V}$
$t_r$	Rise Time	—	84	—		$I_D = 25\text{A}$
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	26	—		$R_G = 3.4\Omega$ , $V_{\text{GS}} = 5.0\text{V}$
$t_f$	Fall Time	—	15	—		$R_D = 1.1\Omega$ , See Fig. 10 ④
$L_D$	Internal Drain Inductance	—	4.5	—	$\text{nH}$	Between lead, 6mm (0.25in.) from package and center of die contact
$L_S$	Internal Source Inductance	—	7.5	—		
$C_{\text{iss}}$	Input Capacitance	—	1700	—	$\text{pF}$	$V_{\text{GS}} = 0\text{V}$
$C_{\text{oss}}$	Output Capacitance	—	400	—		$V_{\text{DS}} = 25\text{V}$
$C_{\text{rss}}$	Reverse Transfer Capacitance	—	150	—		$f = 1.0\text{MHz}$ , See Fig. 5

# Physical Computing



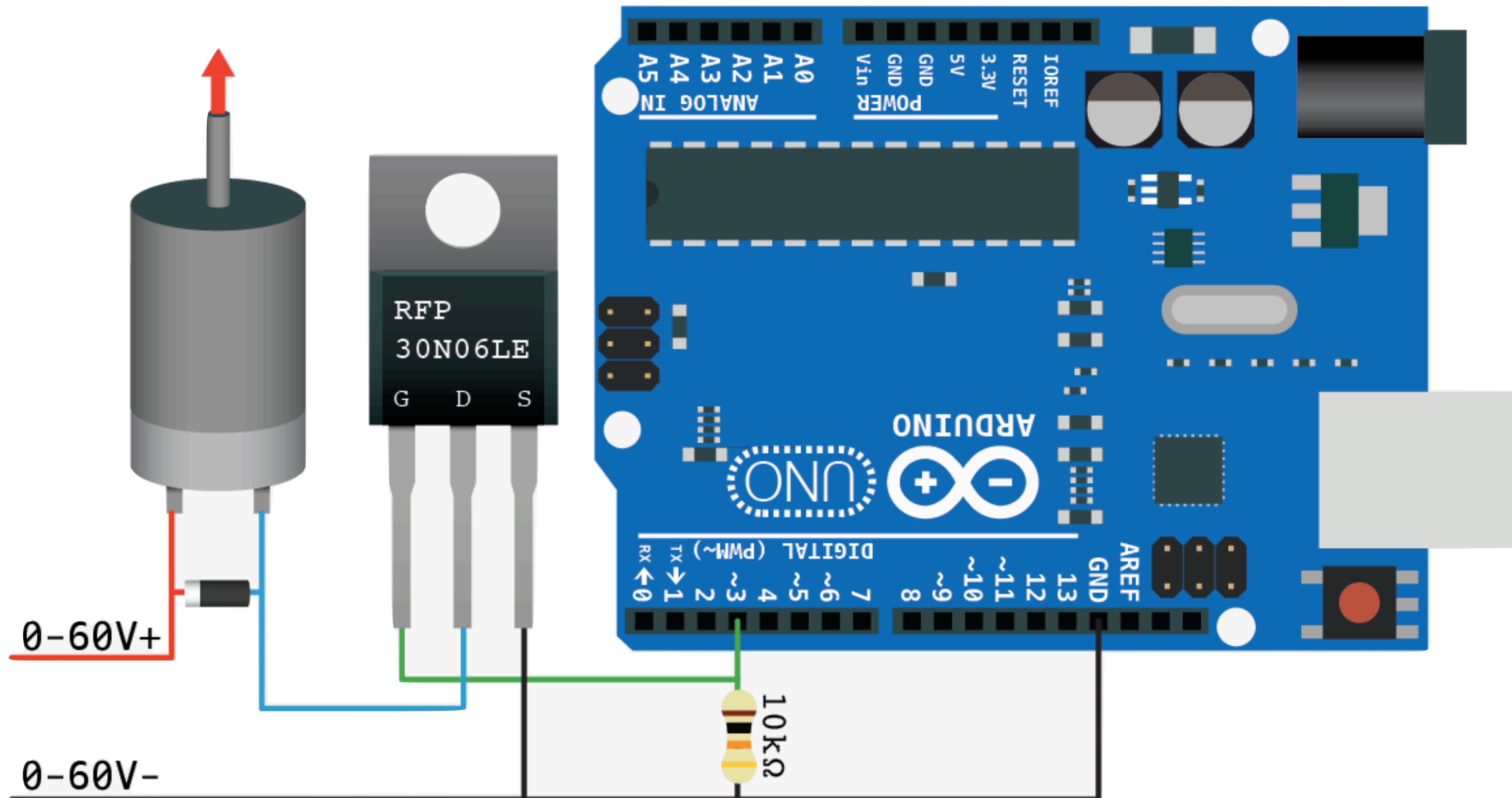
# MOSFETS

# Physical Computing

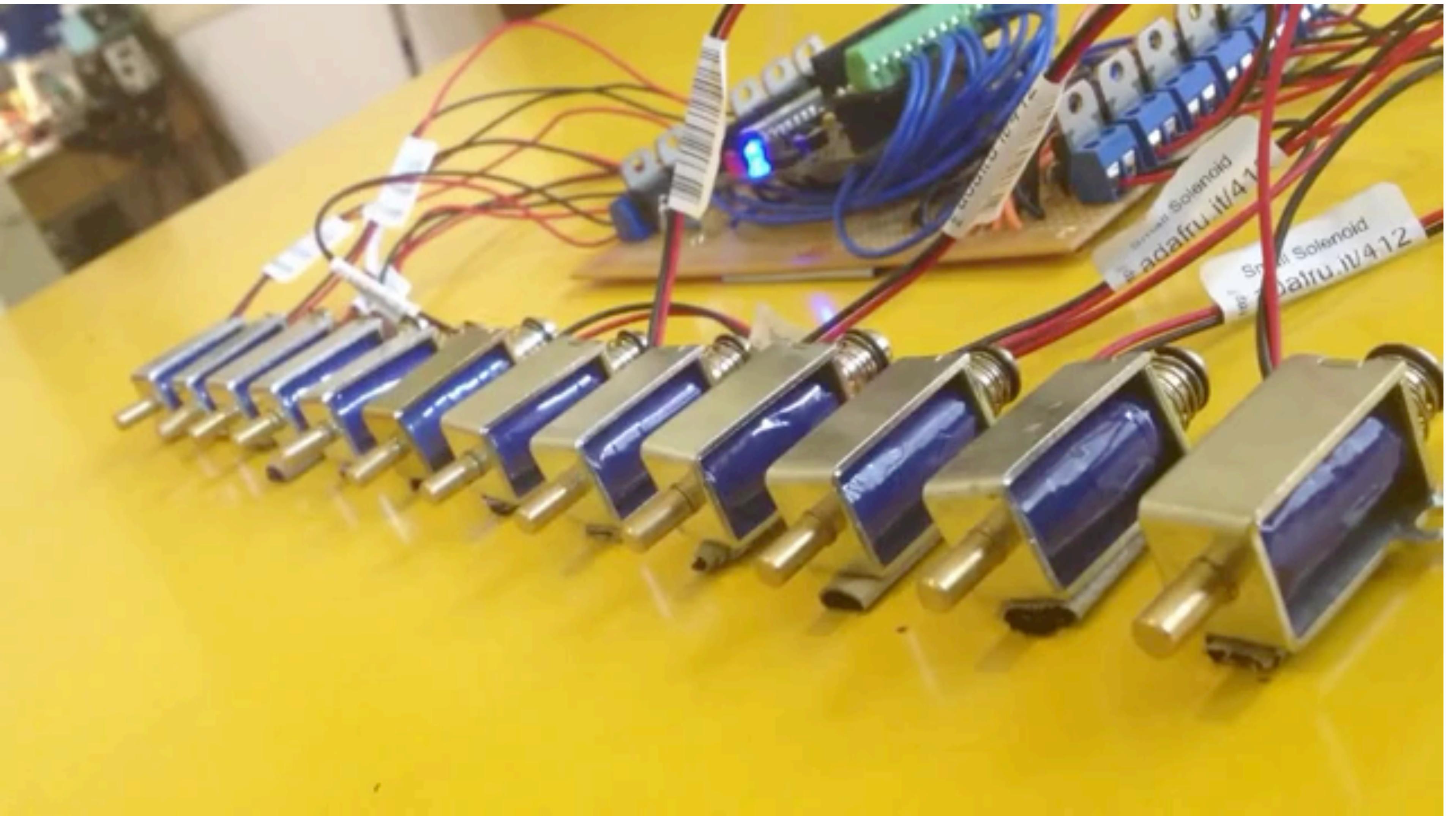


# MOSFETS

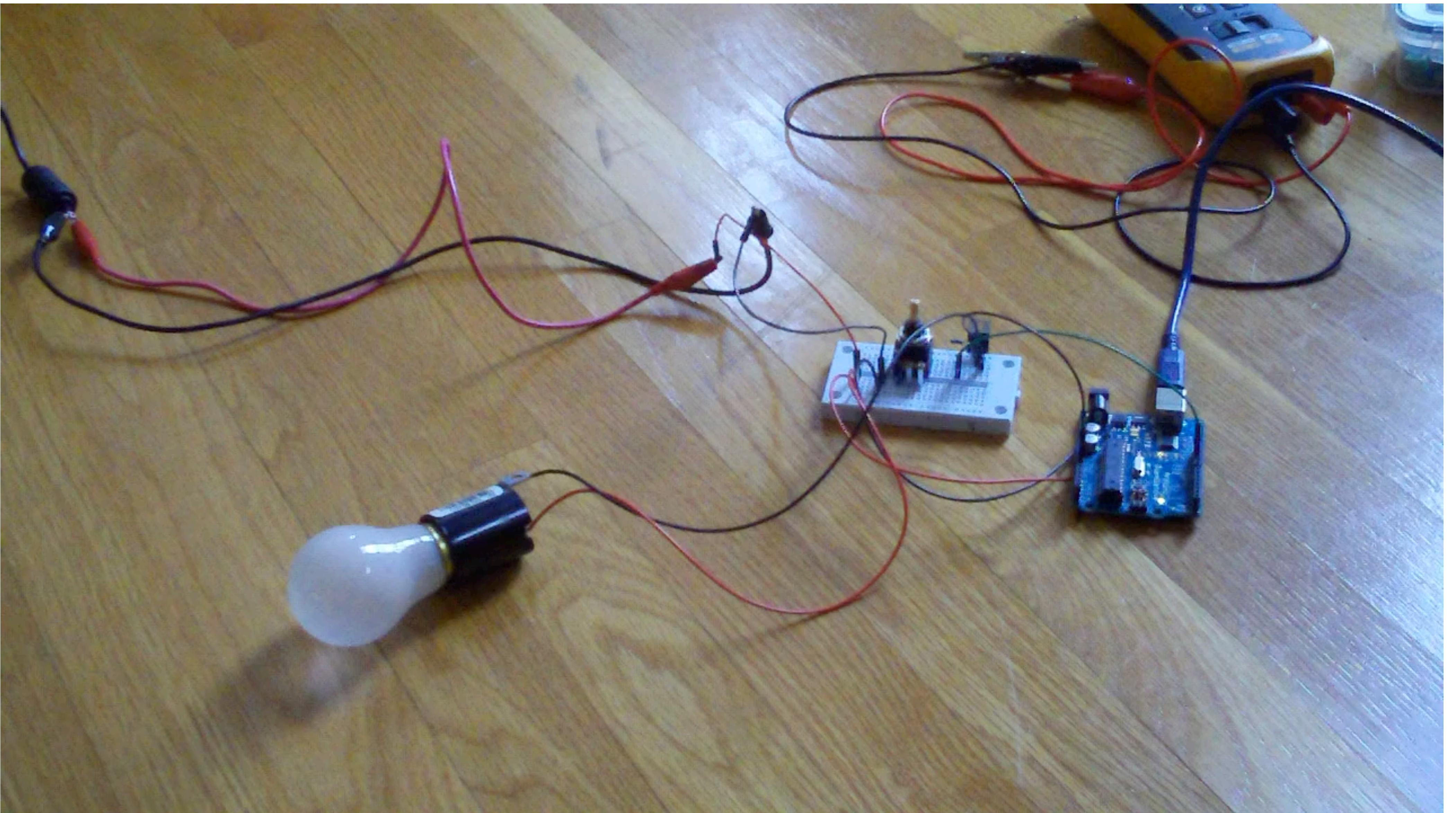
# Physical Computing



# MOSFETS



# MOSFETS



MOSFETS

# Galvanische Trennung

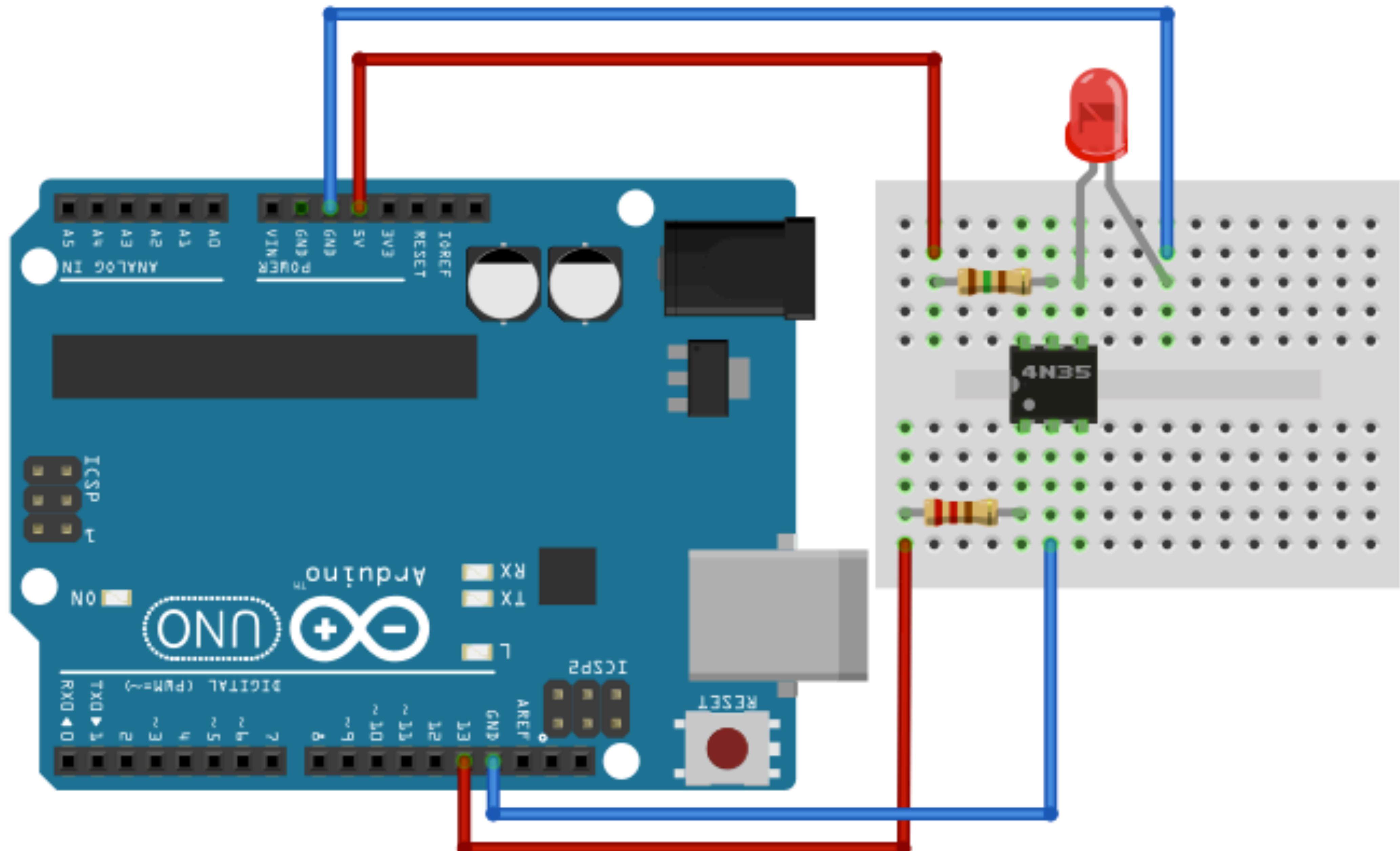
**Masseschleifen / "Brummschleifen"**

**Sicherheit**

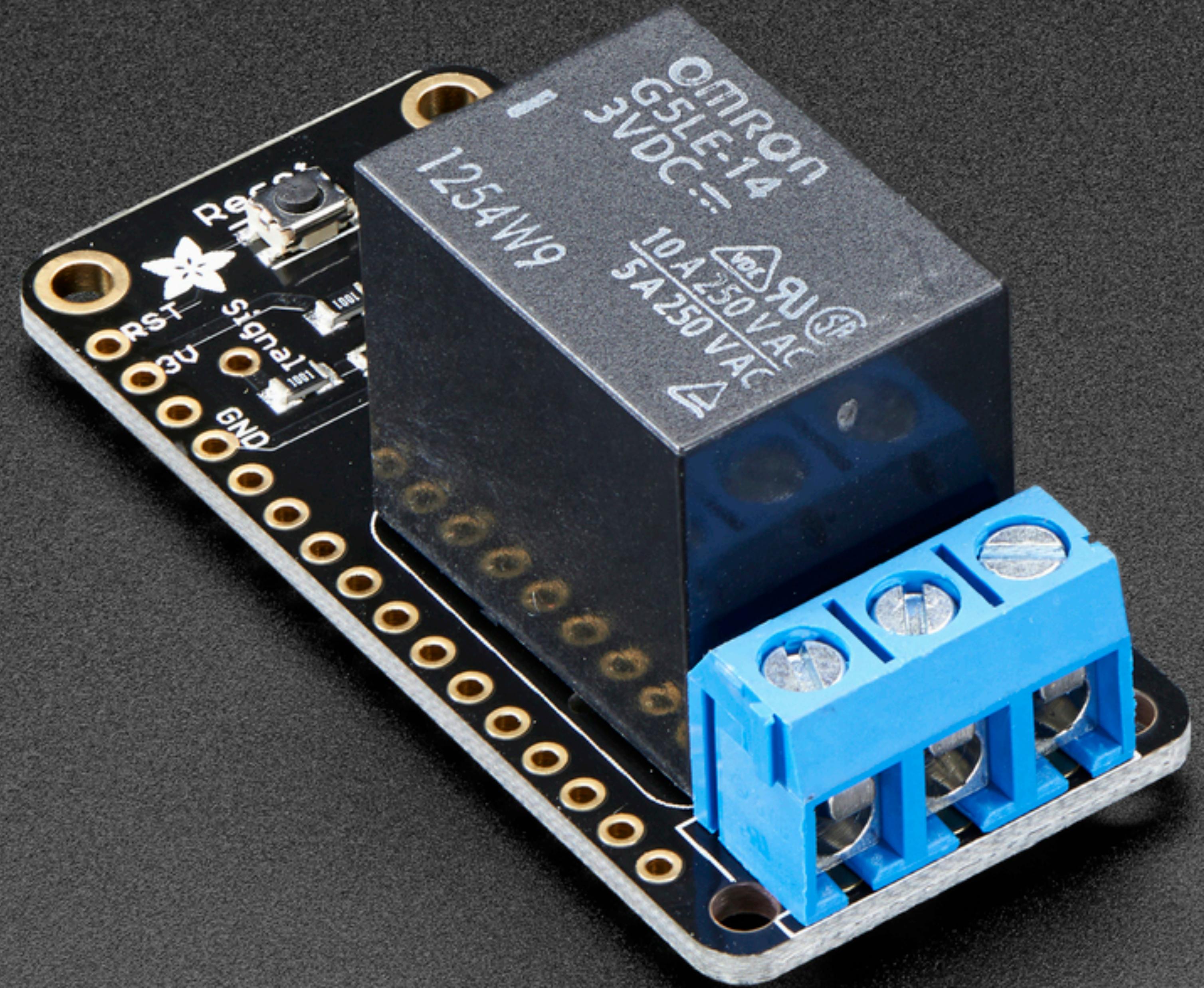
**Schutzmaßnahme**

**Vermeidung von Potentialverschiebungen**

**Galvanische Trennung**



# Optokoppler

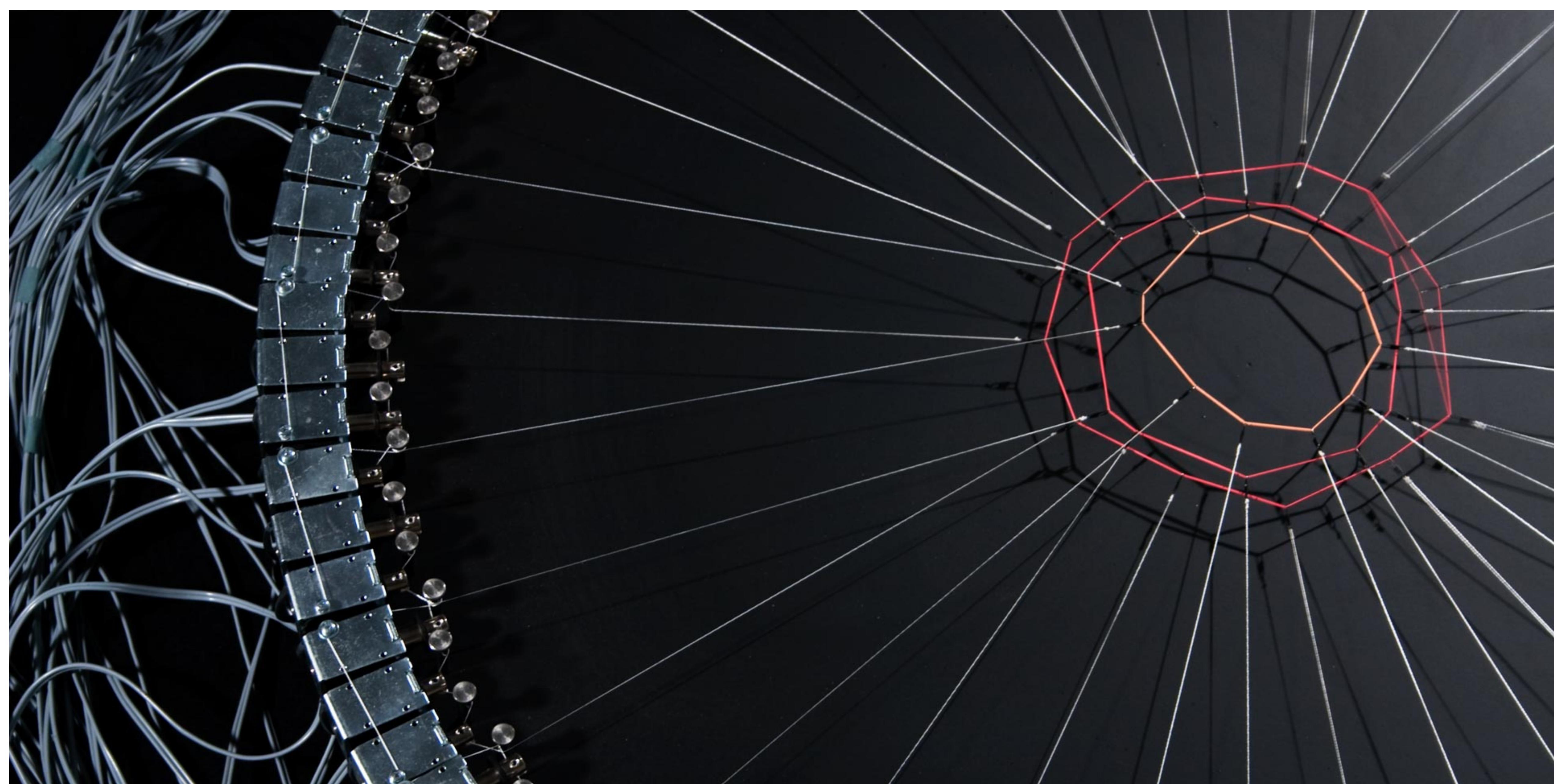


# Relais

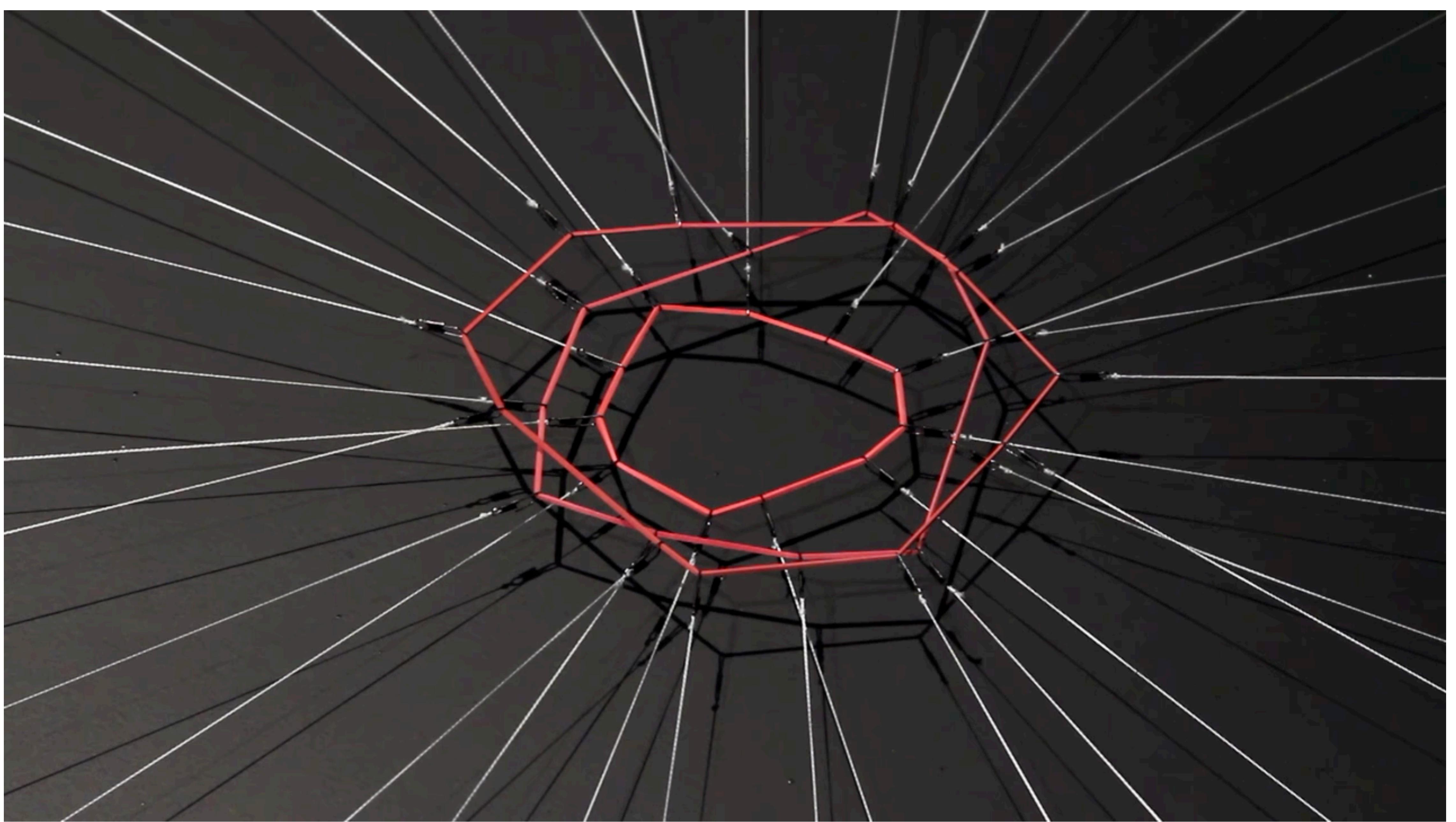
# Anwendungsbeispiele



# The Conversation



# The Conversation



# The Conversation



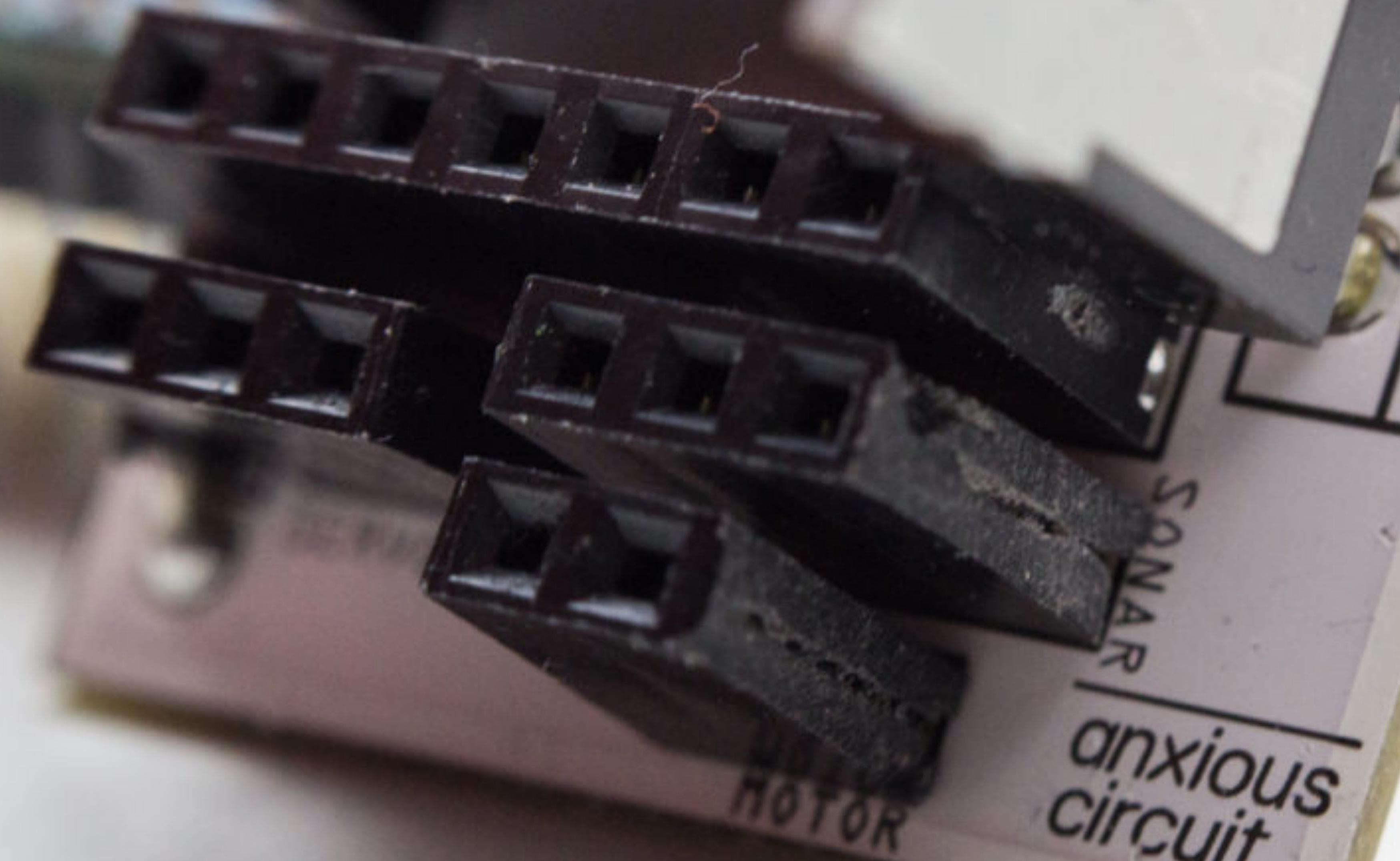
Anxious Lamp



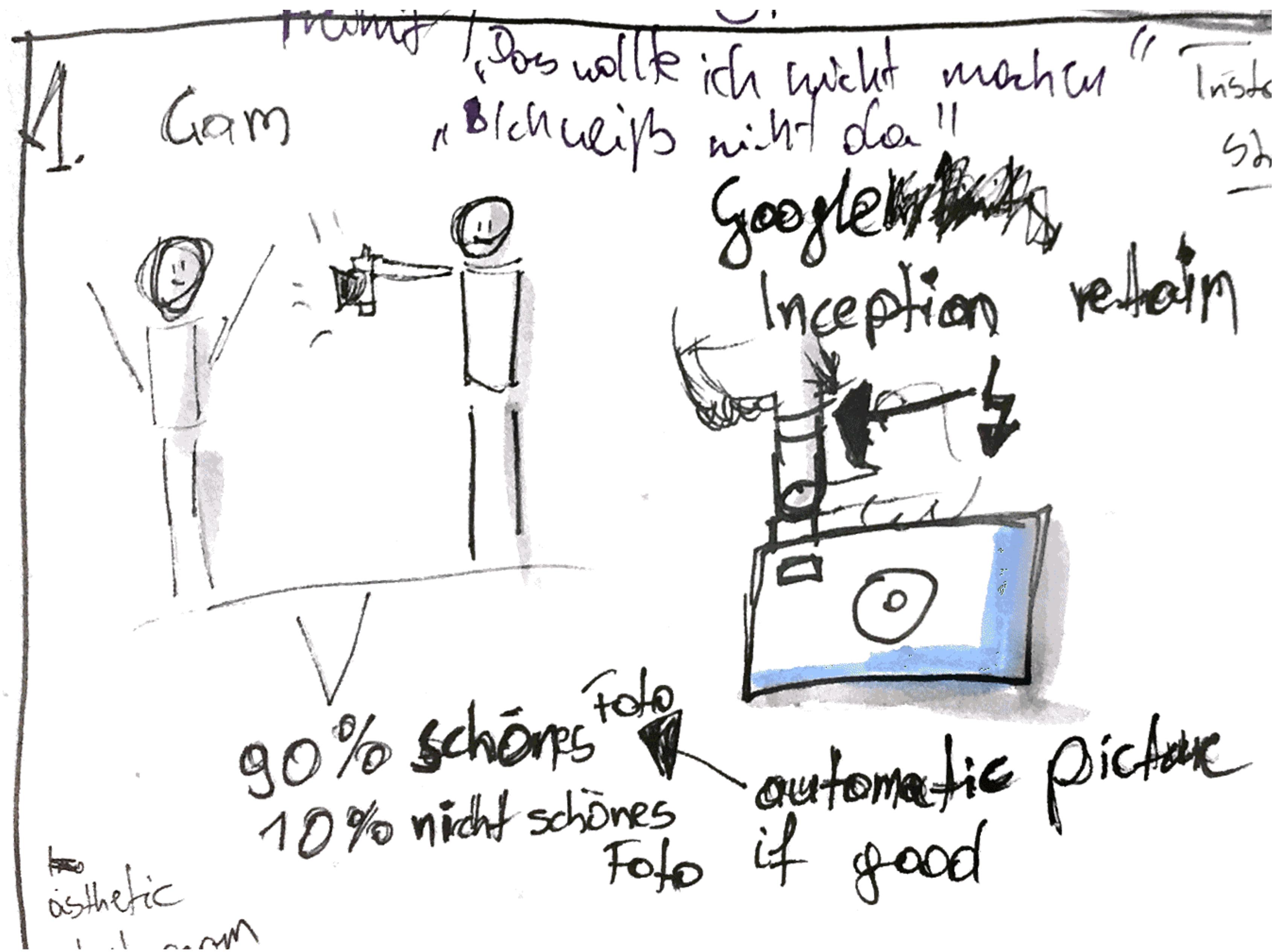
# Anxious Lamp



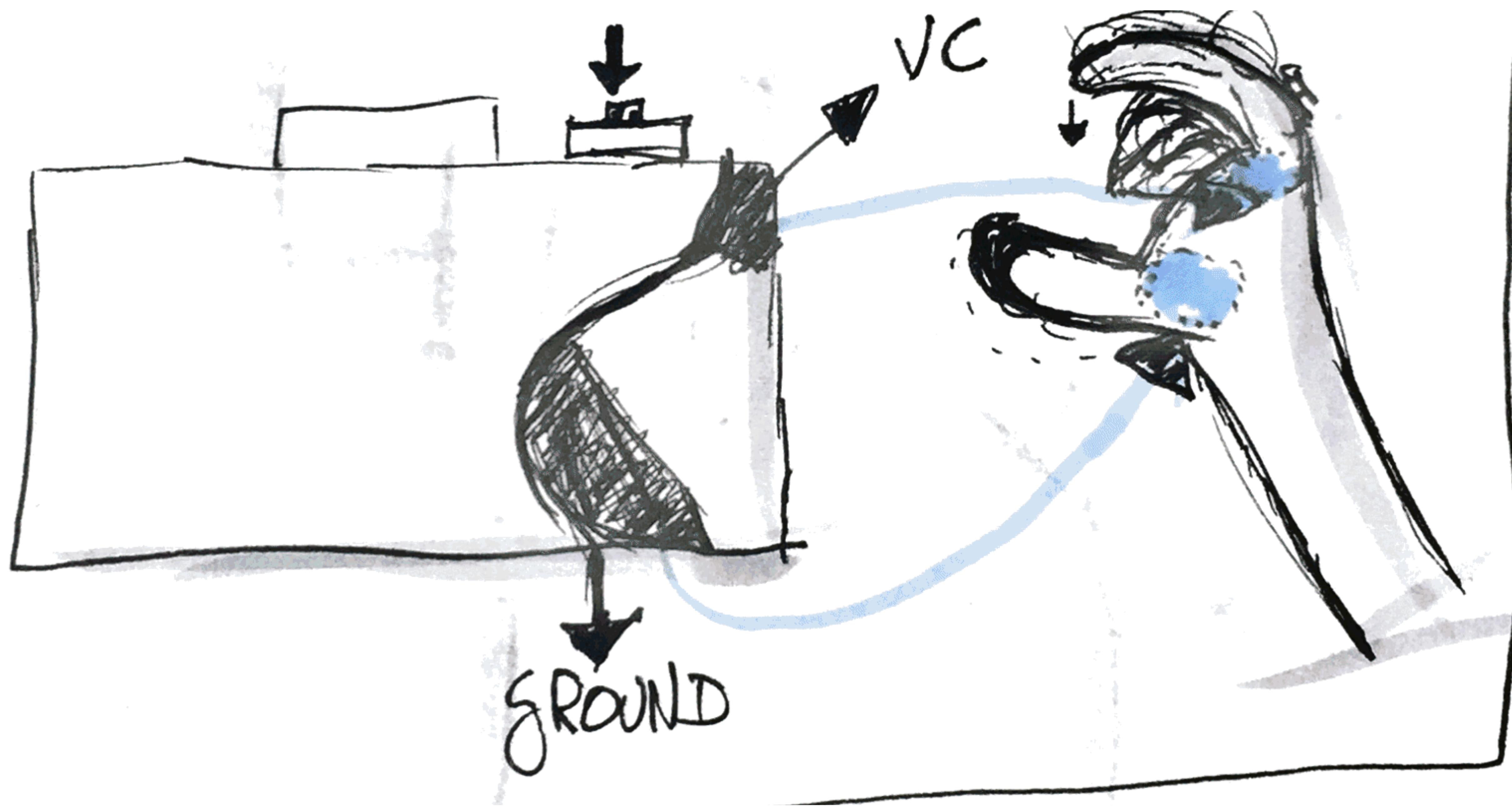
# Anxious Lamp



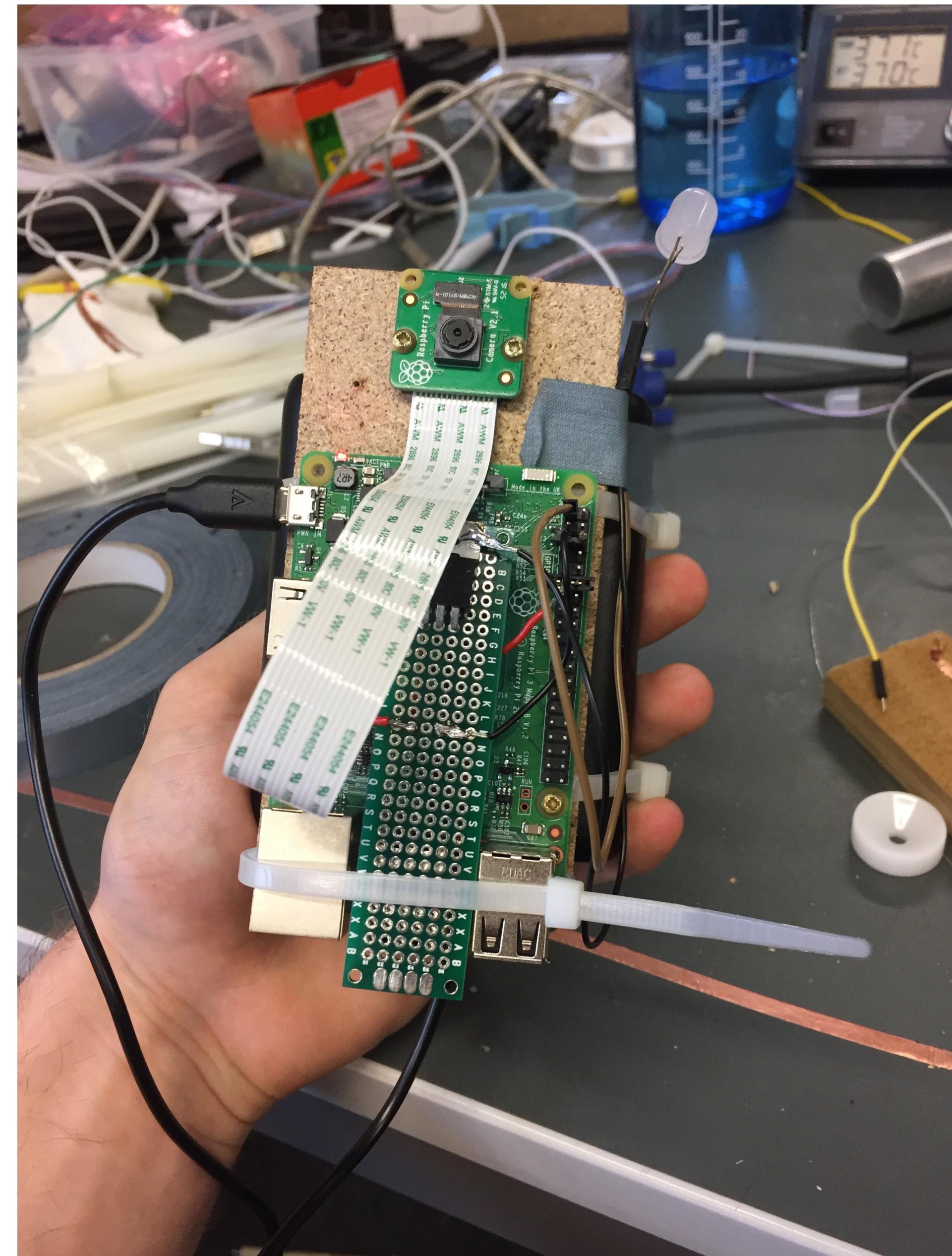
Anxious Lamp



# Prosthetic Photographer



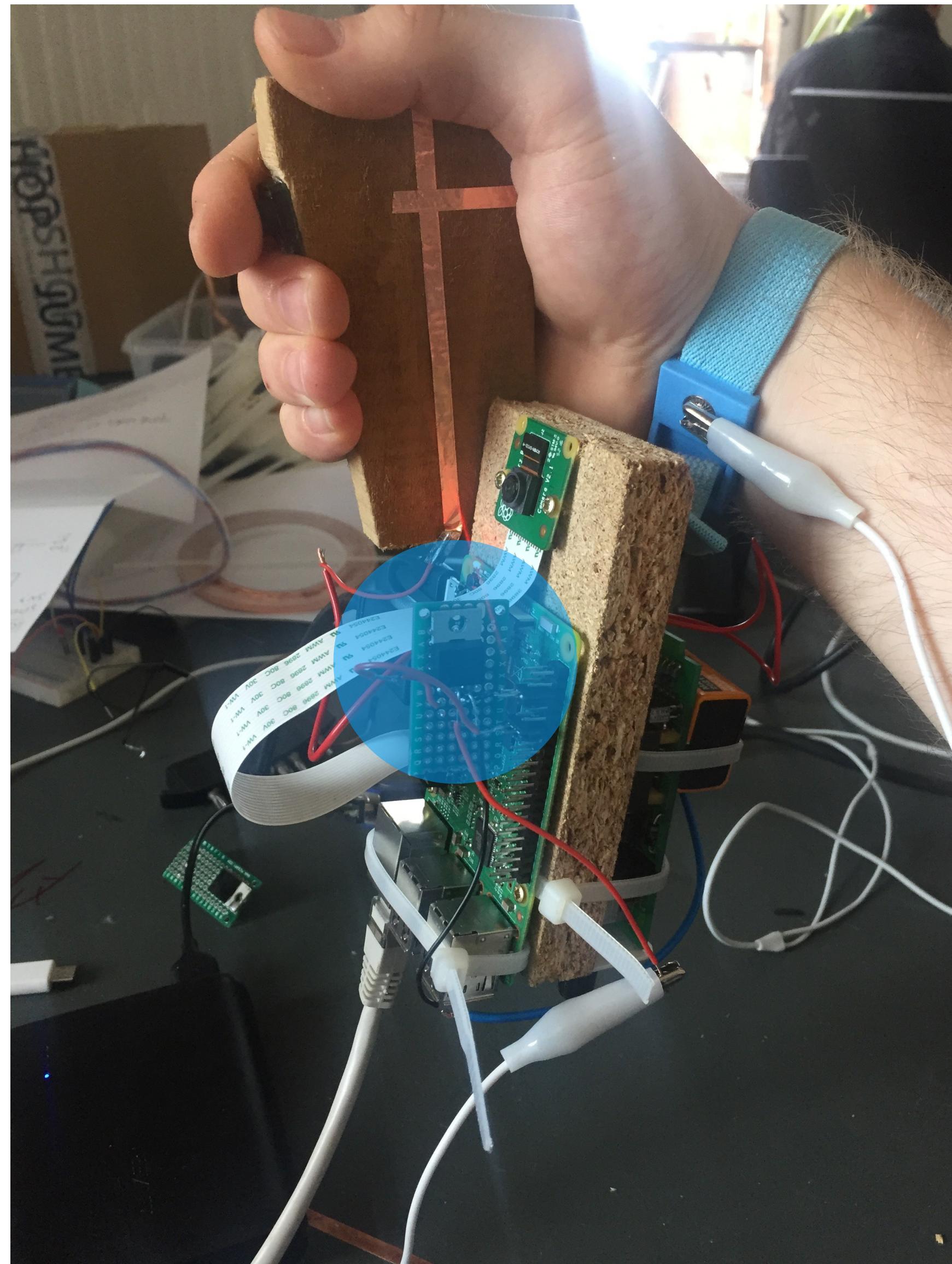
Prosthetic Photographer



# Prosthetic Photographer



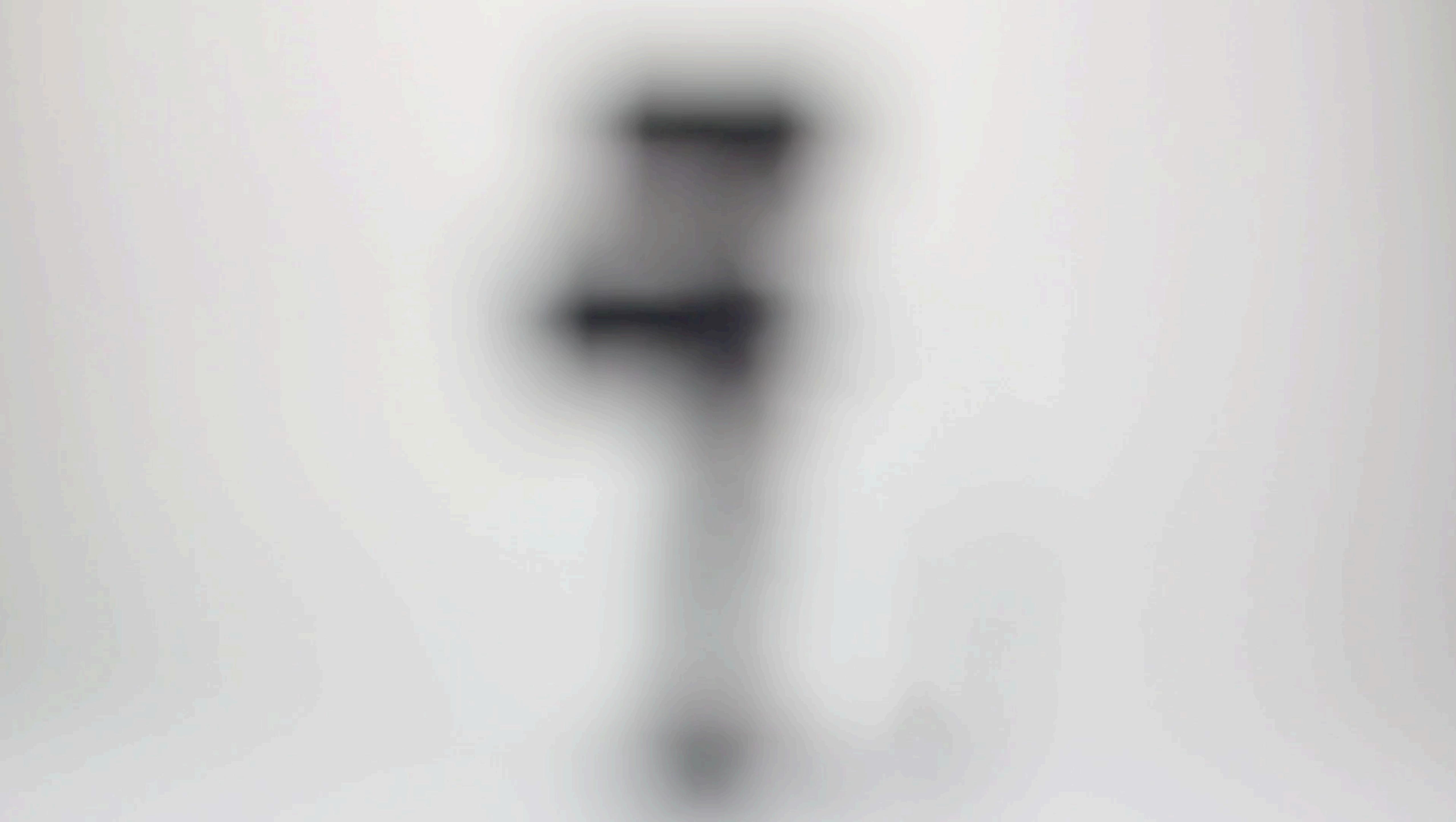
# Prosthetic Photographer



# Prosthetic Photographer



# Prosthetic Photographer

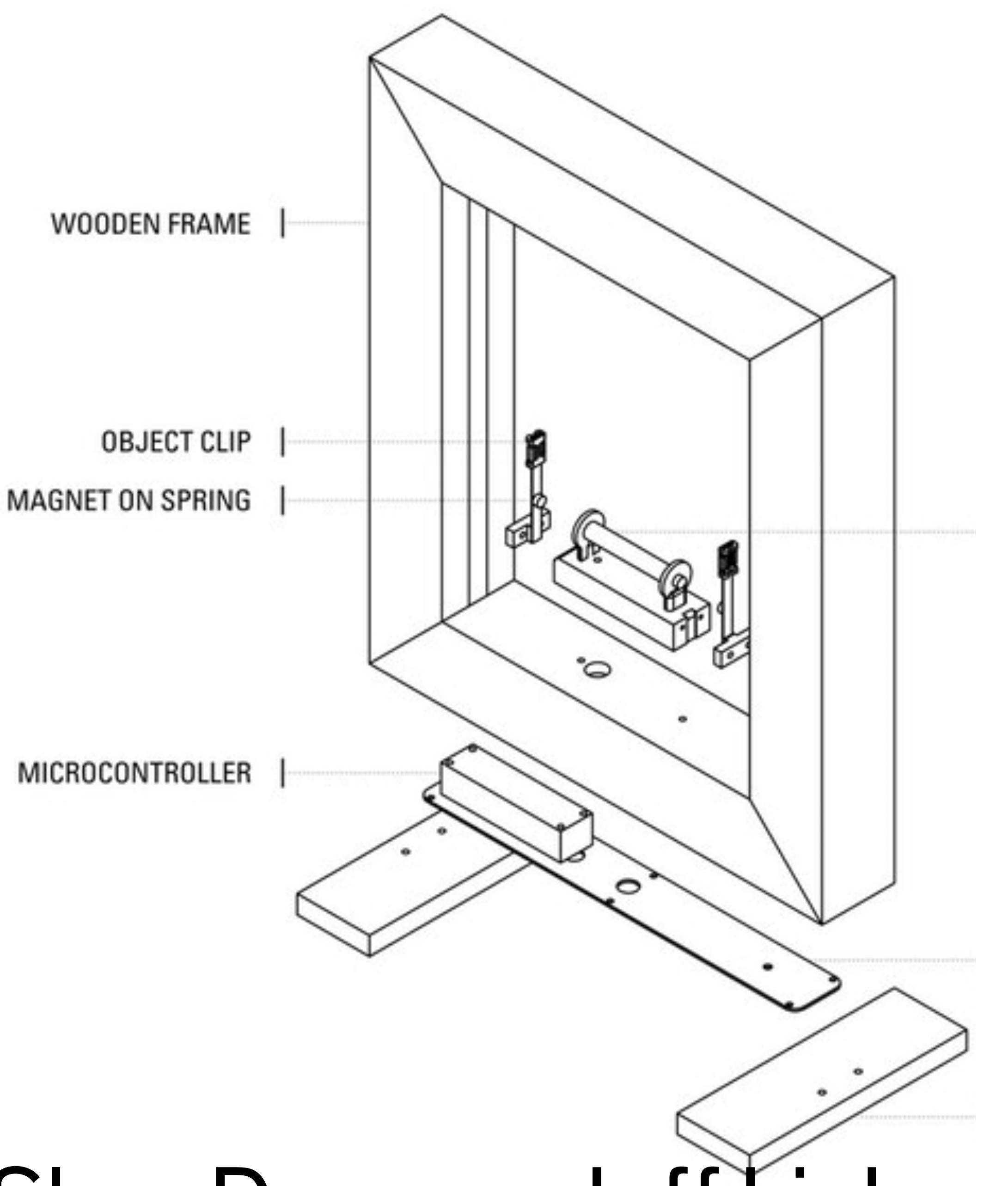


Zeit

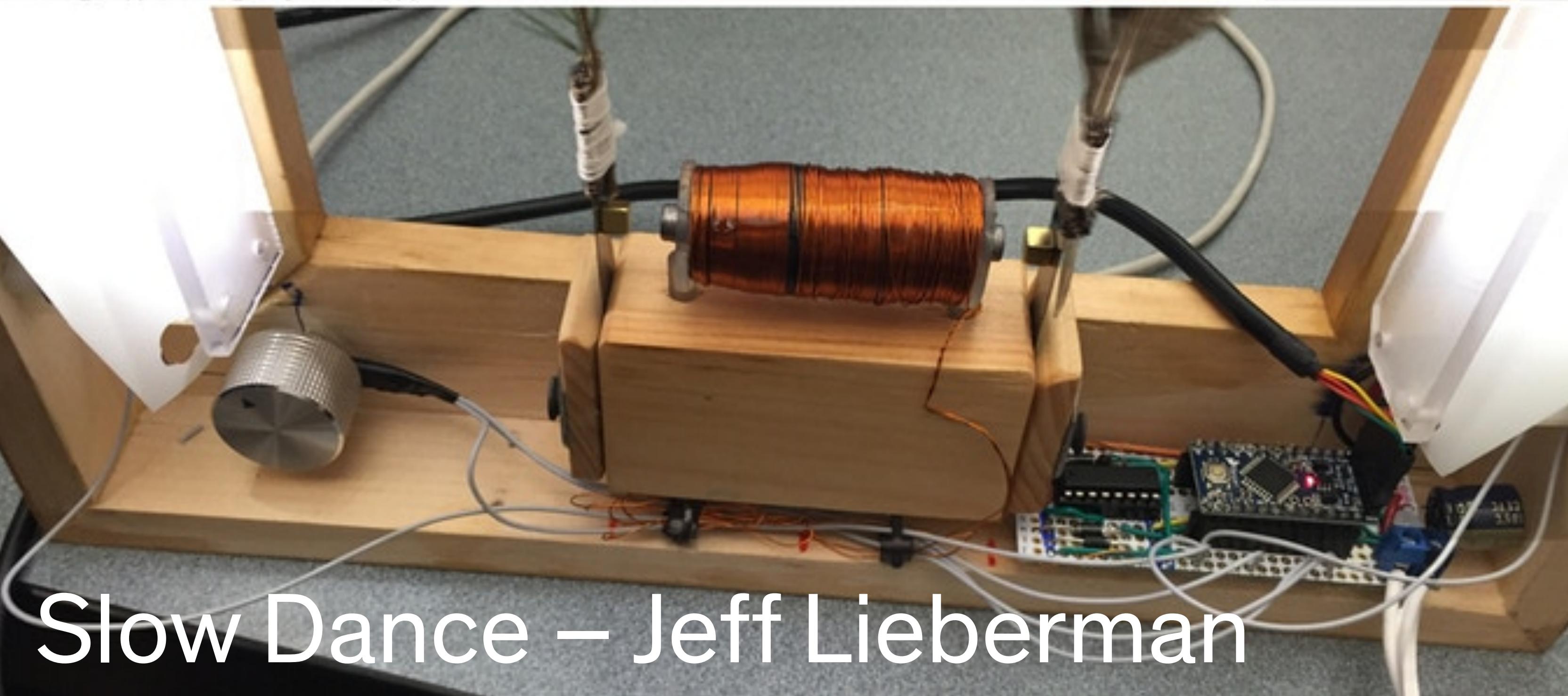
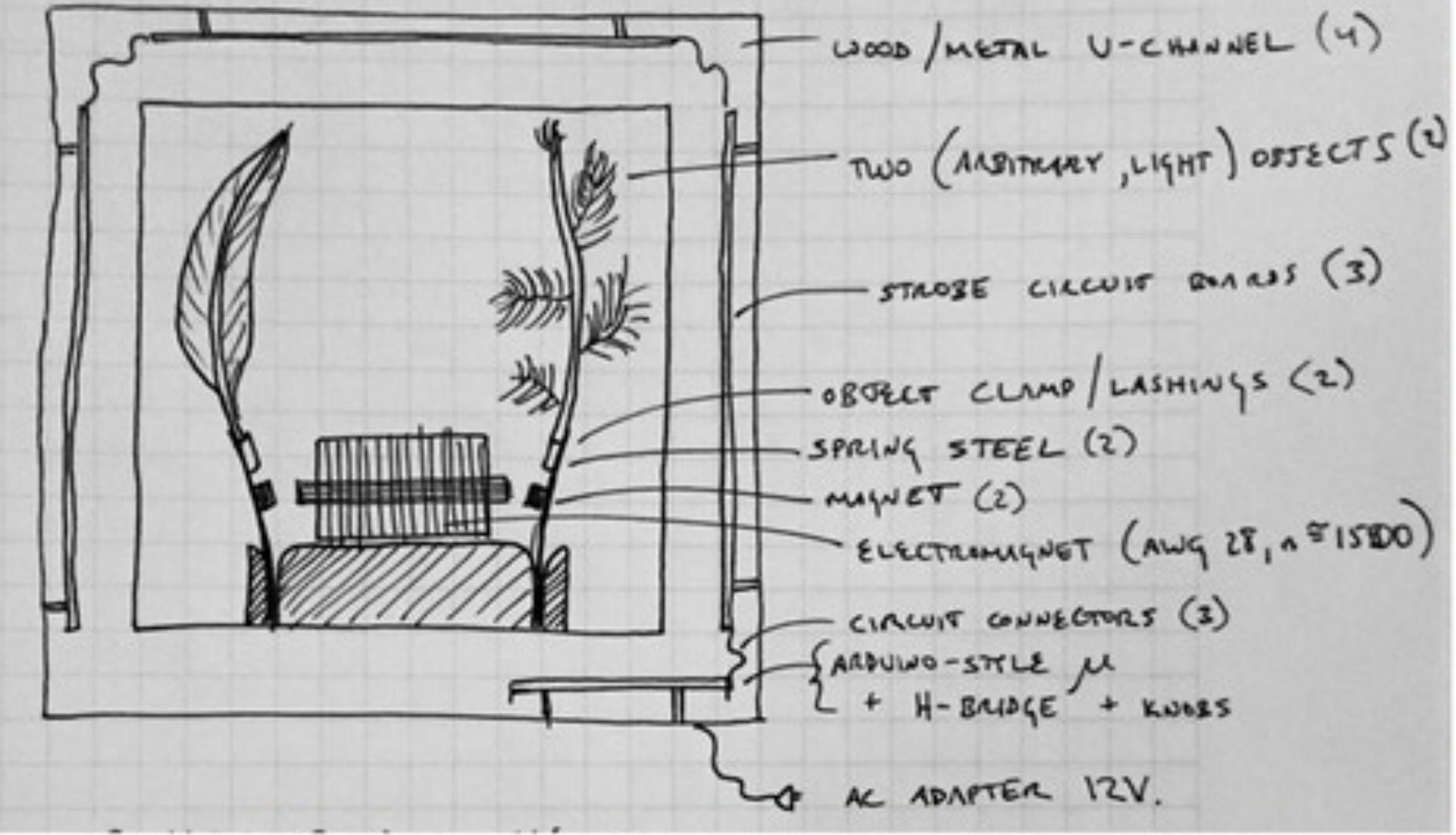
A Million Times – Humans since 1982



Slow Dance – Jeff Lieberman



Slow Dance – Jeff Lieberman



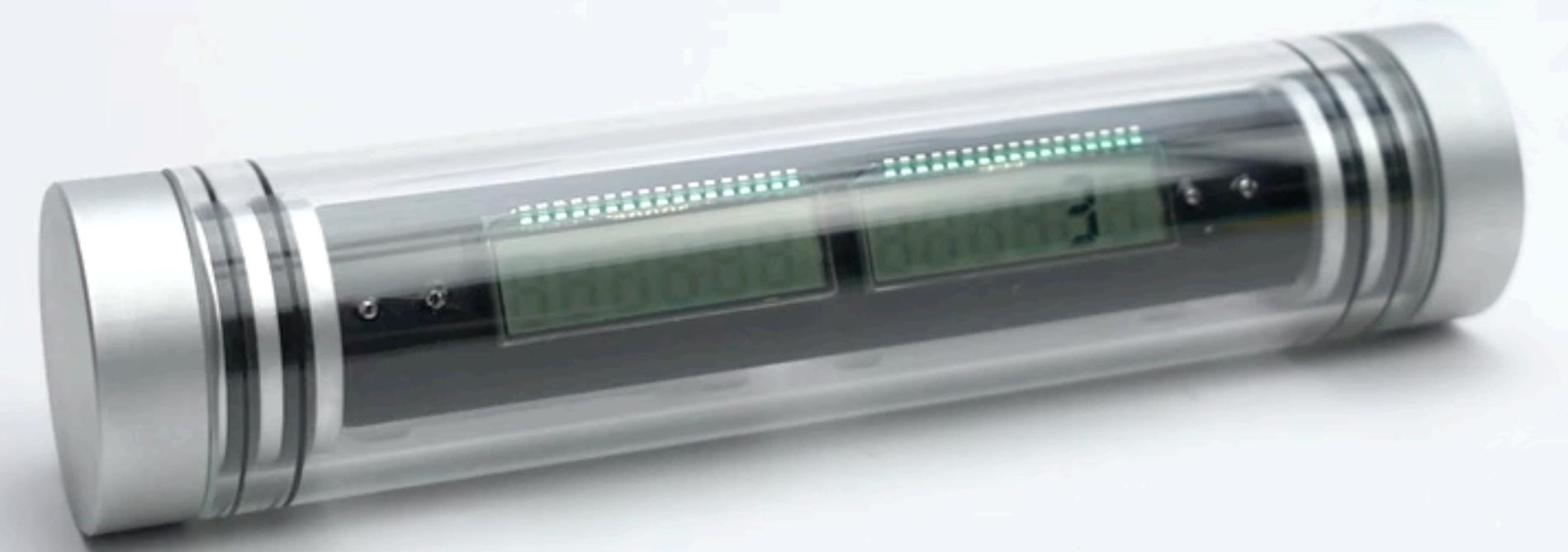
Slow Dance – Jeff Lieberman

Time Since Launch.

Time Since – CW+T



Time Since – CW+T



# Bringt 3 Ideenskizzen zum Thema "Zeit" mit

## \* Individualgespräche

- "Abstract" (bis zu 500 Zeichen)
- Referenzen
- 2D/3D Skizze (Visualisierung)
- Welche Bauteile würdet ihr gerne wie einsetzen?
- Je 1 × A4 Papier pro Ideenskizze

Aufgabe 5 – Bis 06.12.2019

- Beschränkt eure Auswahl auf jeweils eine Eingabe und eine Ausgabe
- Bedient euch auch an bestehenden Dingen und "hackt" sie

# Fragen?